MPQ2288

6V, 16A, Configurable, High-Frequency, Synchronous Buck Converter, with ZDP™, AEC-Q100 Qualified

DESCRIPTION

The MPQ2288 is a configurable, high-frequency, synchronous buck converter with integrated internal high-side and low-side power MOSFETs (HS-FET and LS-FET, respectively). The MPQ2288 operates from a 2.7V to 6V input voltage (V_{IN}) range and provides up to 16A of highly efficient output current (I_{OUT}) with fixed-frequency, zero-delay pulse-width modulation (PWM) (ZDP™) control for optimal transient response.

The configurable 2MHz to 4MHz switching frequency (f_{SW}) during forced continuous conduction mode (FCCM) greatly reduces the external inductance and capacitance. Internal feedback and compensation minimize the external component count and improve accuracy.

Full protection features include short-circuit protection (SCP), over-current protection (OCP), input over-voltage protection (OVP), output OVP, and thermal shutdown. These protections provide reliable, fault-tolerant operation.

The digital interface features packeting error checking (PEC), and the integrated multi-page one-time programmable (OTP) memory allows for a high degree of configurability.

The MPQ2288 is available in a QFN-18 (3mmx4mm) package with wettable flanks, and is available in AEC-Q100 Grade 1.

FEATURES

- Designed for Automotive Point-of-Load (PoL) Applications
  - 2.7V to 6V Input Voltage (V_{IN}) Range
  - 16A Continuous Output Current (I_{OUT})
  - 1.0% Output Regulation Accuracy
  - Differential Output Voltage (V_{OUT}) Sense
  - Internal 6mΩ High-Side MOSFET (HS-FET) and 4mΩ Low-Side MOSFET (LS-FET)

FEATURES *(continued)*

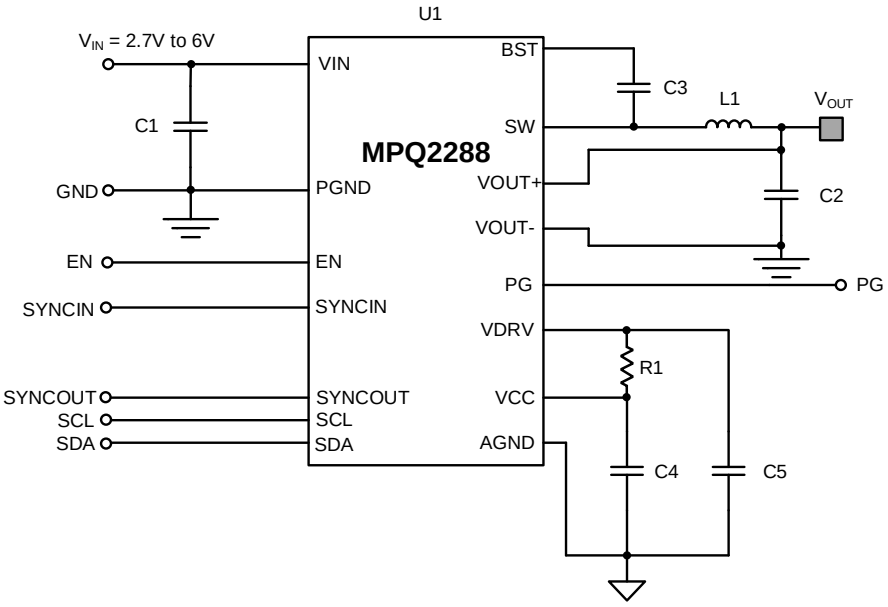
  - Configurable 2MHz to 4MHz Switching Frequency (f_{SW})
  - Available in AEC-Q100 Grade 1
- Optimized for EMC/EMI
  - Synchronizable Input/Output
  - Frequency Spread Spectrum (FSS)
- Flexible Application with Digital Interface
  - Digital Interface with Cyclic Redundancy Check (CRC)
  - Converter On/Off
  - 0.5V to 3.6V V_{OUT} Setting Range
  - Fault Detection
  - Factory-Configurable Multi-Page One-Time Programmable (OTP) Memory
- Protections
  - Peak and Valley Current Limits
  - Over-Current Protection (OCP)
  - Short Circuit Protection (SCP)
  - Output Over-Voltage Protection (OVP)
  - Input OVP
  - Thermal Warning
  - Thermal Shutdown
- Additional Features
  - Soft Start (SS) and Soft Shutdown
  - Power Good
  - Available in a QFN-18 (3mmx4mm) Package with Wettable Flanks
- Functional Safety System Design Capable
  - MPSafe ™ Compatible – Functional Safety Supporting Document Available

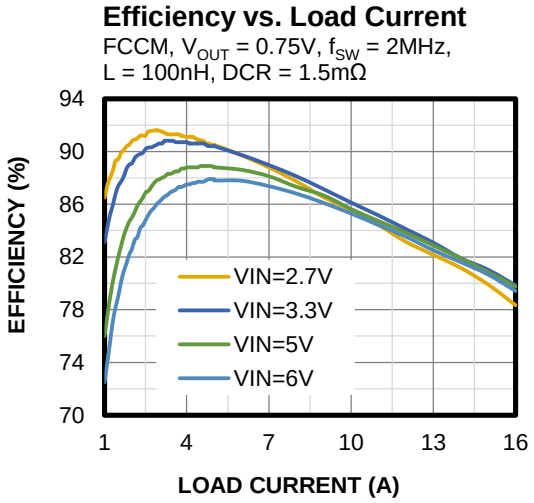
MPSafe™ FuSa Compatible

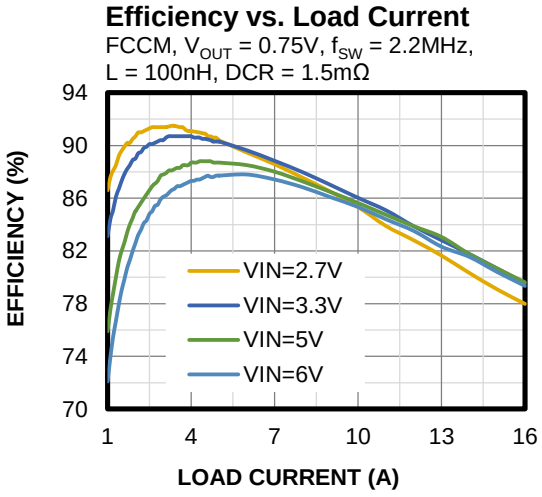
APPLICATIONS

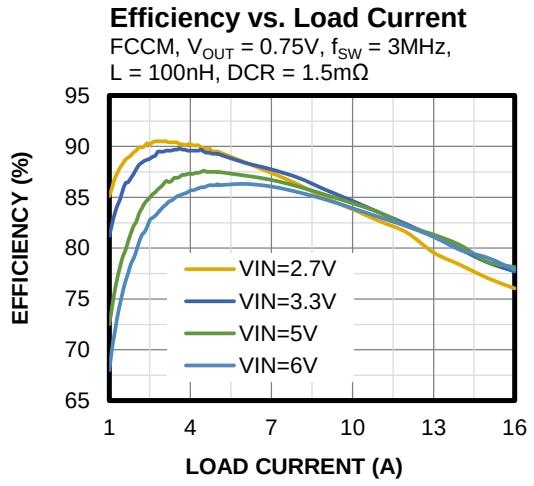
- Advanced Driver-Assistance Systems (ADAS)
- Infotainment
- System-on-Chip (SoC) System Cores
- DDR Memory

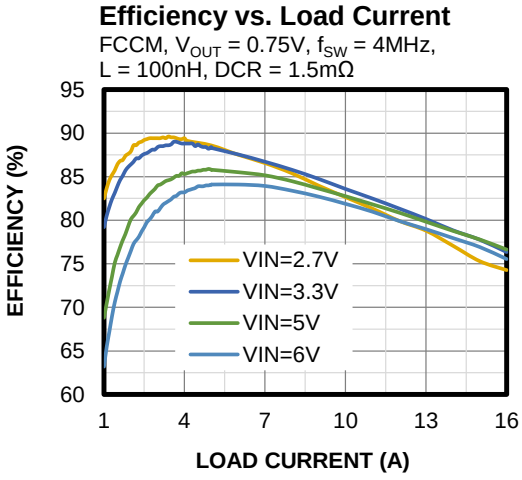
TYPICAL APPLICATION











ORDERING INFORMATION

Part Number*	Package	Top Marking	MSL Rating***
MPQ2288GLE-xxxx-AEC1 **, ****	QFN-18 (3mmx4mm)	*See Below*	1

* For Tape & Reel, add suffix -Z (e.g. MPQ2288GLE-xxxx-AEC1-Z).

** “xxxx” is the configuration code identifier for the register settings stored in the OTP register. The first value must be a numerical value (0–9), while the last three values can be a hexadecimal value between 0 and F. The default code is “0000”. Contact an MPS FAE to create this unique number.

***Moisture Sensitivity Level Rating

**** Wettable flank

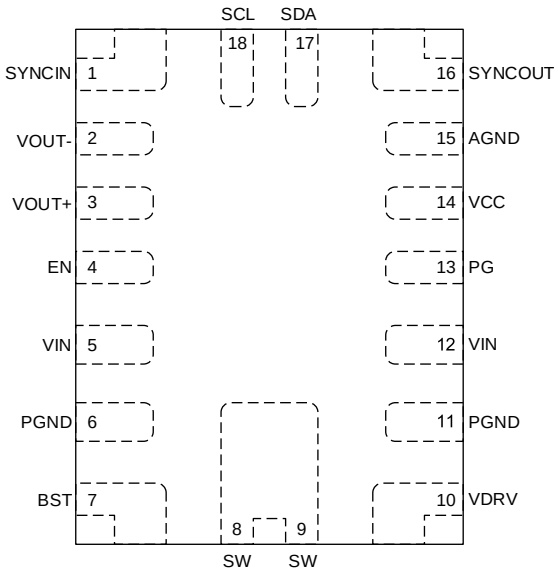
TOP MARKING

MPYW
2288
LLL
E

MP: MPS prefix
Y: Year code
W: Week code
2288: Part number
LLL: Lot number
E: Wettable Flank

PACKAGE REFERENCE

TOP VIEW



QFN-18 (3mmx4mm)

PIN FUNCTIONS

Pin #	Name	Description
1	SYNCIN	**Synchronous input.** Apply a clock signal to the SYNCN pin to synchronize the switching frequency (f_{SW}) to the external clock. Use an external clock to enter forced continuous conduction mode (FCCM). The MPQ2288 can also be set to FCCM via the digital interface. Connect SYNCIN to GND via a resistor if this pin is not used.
2	VOUT-	**Output negative differential sense.** Connect VOUT- to the negative side of the output capacitor (C_{OUT}).
3	VOUT+	**Output positive differential sense.** Connect VOUT+ to the positive side of C_{OUT}.
4	EN	**Enable.** Pull the EN pin above the specified threshold (1.2V) to enable the chip. Pull it below the specified threshold (1.1V) to shut down the chip. There is an internal 200kΩ pull-down resistor. This pin can be floated if it is not used.
5, 12	VIN	**Input supply.** The VIN pins are connected internally. VIN supplies power to the internal low-dropout (LDO) regulator, control circuitry, and the power MOSFET connected to SW. It is recommended to connect a decoupling capacitor from VIN to ground, placed close to VIN, to minimize switching spikes.
6, 11	PGND	**Power ground.** The PGND pins are connected internally.
7	BST	**Bootstrap supply.** The BST pin is the positive power supply for the high-side MOSFET (HS-FET) driver connected to SW. Connect a 0.22μF bypass capacitor between the BST and SW pins.
8,9	SW	**Switch node**. SW is the output of the internal power MOSFET. Connect SW to the power inductor.
10	VDRV	**Internal LDO decoupling pin and supply input for the internal power circuitry.** Connect a 4.7μF capacitor from the VDRV pin to PGND. Connect a 2.2Ω resistor between VCC and VDRV.
13	PG	**Power good indicator.** The PG pin is an open-drain output. Connect PG to VCC using an external resistor. PG asserts if the output voltage (V_{OUT}) is not within regulation, or if an error has occurred. This pin can be configured via the digital interface. If this pin is not used, connect it to AGND directly or through a resistor. See the Power Good (PG) Indicator section on page 32 for detailed description of the PG state.
14	VCC	**Supply input for the internal analog and digital circuitry**. Connect a 2.2μF capacitor from VCC to AGND. Connect a 2.2Ω resistor between VCC and VDRV.
15	AGND	**Analog ground.**
16	SYNCOUT	**Synchronous output.** The SYNCOUT pin outputs a 0° or 180° out-of-phase clock to the other devices. This pin can be floated if it is not used.
17	SDA	**Digital interface serial data.** This pin is an open-drain port and cannot be floated. Use an external pull-up resistor to connect this pin to the supply rail of the digital interface. Connect this pin to GND if it is not used.
18	SCL	**Digital interface serial clock.** This pin is an open-drain port and cannot be floated. Use an external pull-up resistor to connect this pin to the supply rail of the digital interface. Connect this pin to GND if it is not used.

ABSOLUTE MAXIMUM RATINGS (1)

V_{IN}, V_{SW} .....-0.3V to +8.5V
V_{BST} ..... -0.3V to 4V + V_{SW}
All other pins .....-0.3V to +4V
Continuous power dissipation (T_A = 25°C) (2) (6)
QFN-18 (3mmx4mm) 4.59W
Junction temperature (T_J) .....150°C
Lead temperature .....260°C

ESD Ratings

Human body model (HBM) .....Class 2 (3)
Charged-device model (CDM) .....Class 2b (4)

Recommended Operating Conditions

Input voltage (V_{IN}) .....2.7V to 6V
Output voltage (V_{OUT}).....0.5V to 3.6V
Operating junction temp (T_J).... -40°C to +150°C

Thermal Resistance θ_{JA} θ_{JC}

QFN-18 (3mmx4mm)
JESD51-7……44.67....4.2…°C/W (5)
EVQ2288-L-00A……27.22……..°C/W (6)

Ψ_{JT}
JESD51-7…..1.3... °C/W (5)
EVQ2288-L-00A.....2.86... °C/W (6)

Notes:

1) Exceeding these ratings may damage the device.
2) The maximum allowable power dissipation is a function of the maximum junction temperature, T_J (MAX), the junction-to-ambient thermal resistance, θ_{JA}, and the ambient temperature, T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX) - T_A) / θ_{JA}. Exceeding the maximum allowable power dissipation can cause excessive die temperature, and the regulator may go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
3) Per AEC-Q100-002.
4) Per AEC-Q100-011.
5) Measured on a JESD51-7, 4-layer PCB. The values given in this table are only valid for comparison with other packages and cannot be used for design purposes. These values were calculated in accordance with JESD51-7, and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application. The value of θ_{JC} shows the thermal resistance from junction-to-case bottom, and the Ψ_{JT} value shows the characterization parameter from the junction-to-case top.
6) Measured on an MPS standard EVB, 8.3cmx8.3cm, 2oz copper thickness, 4-layer PCB, the value of Ψ_{JT} shows the characterization parameter from the junction-to-case top.

ELECTRICAL CHARACTERISTICS

Typical values are V_{IN} = 5V, V_{EN} = 2V, T_J = 25°C, all voltages with respect to ground, unless otherwise noted. Minimum and maximum values are at V_{IN} = 5V, V_{EN} = 2V, T_J = -40°C to +150°C, all voltages with respect to ground, guaranteed by characterization, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Input Supply Voltage (V_{IN})						
V_{IN} under-voltage lockout (UVLO) rising threshold	$V_{IN\_UVLO\_RISING}$		2.4		2.7	V
V_{IN} UVLO hysteresis	$V_{IN\_UVLO\_HYS}$			150		mV
VIN quiescent current	I_{Q_ON}	Buck on, no switching			7	mA
VIN shutdown current	I_{Q_OFF}	Buck off, enable low			20	µA
VDRV Regulator						
VDRV regulation voltage	V_{DRV}	C_{VCC} = 2.2µF, I_{VCC} = 20mA, V_{IN} = 5V	3.1	3.3	3.5	V
VDRV current limit	I_{VDRV}	V_{DRV} = 2.7V, V_{IN} = 5V		100		mA
		V_{DRV} = 0V, V_{IN} = 5V		100		mA
Oscillator						
Switching frequency range (9)	f_{SW}		2		4	MHz
Switching frequency accuracy	f_{SW_ACC}		-10		+10	%
Minimum on time	t_{ON_MIN}	V_{IN} = 5V, V_{OUTP} = 2 x VOUT_SCALE		26	45	ns
Minimum off time	t_{OFF_MIN}			100		ns
Minimum frequency	f_{SW_MIN}	Ultrasonic mode (USM) enabled	40		50	kHz
Frequency spread spectrum (FSS) modulation	f_{SS_SPREAD}			-7.5		%
				+6.5		%
FSS modulation frequency rate	f_{SS_RATE}			9		kHz
Dynamic Output Voltage (V_{OUT})						
V_{OUT} range (9) (10)	V_{OUT}		0.5		3.6	V
V_{OUT} accuracy	V_{OUT_ACC}	V_{OUT} ≥ 0.5V x VOUT_SCALE, as a percentage of V_{OUT}, I_{OUT} = 0A	-1		+1	%
		VOUT_SCALE = 2, V_{OUT} < 1V, I_{OUT} = 0A	-10		+10	mV
V_{OUT} start-up slew rate range (9)	$V_{OUTSLEW\_ST}$		1.25		10	mV/µs
V_{OUT} start-up slew rate accuracy	$V_{OUTSLEW\_ST\_ACC}$		-15		+15	%
V_{OUT} shutdown slew rate range (9)	$V_{OUTSLEW\_SP}$		1.25		10	mV/µs
V_{OUT} shutdown slew rate accuracy	$V_{OUTSLEW\_SP\_ACC}$		-15		+15	%
V_{OUT} dynamic slew rate range (9)	$V_{OUTSLEW}$		2.5		20	mV/µs
V_{OUT} dynamic slew rate accuracy	$V_{OUTSLEW\_ACC}$		-15		+15	%

ELECTRICAL CHARACTERISTICS *(continued)*

Typical values are V_{IN} = 5V, V_{EN} = 2V, T_J = 25°C, all voltages with respect to ground, unless otherwise noted. Minimum and maximum values are at V_{IN} = 5V, V_{EN} = 2V, T_J = -40°C to +150°C, all voltages with respect to ground, guaranteed by characterization, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Power Stage						
High-side MOSFET (HS-FET) on resistance	$R_{DS(ON)\_HS}$			6	12	mΩ
Low-side MOSFET (LS-FET) on resistance	$R_{DS(ON)\_LS}$			4	8	mΩ
HS-FET leakage current	I_{LKG_HS}	V_{DS} = 6V			200	μA
LS-FET leakage current	I_{LKG_LS}	V_{DS} = 6V			200	μA
Peak current limit (I_{LIMIT}) (9)	I_{LIMIT_HS}	ILIM_SCALE = 150%	25	28	35	A
Valley I_{LIMIT} (9)	I_{LIMIT_LS}	ILIM_SCALE = 150%	16	21	25	A
Reverse current limit	$I_{LIMIT\_REVERSE}$		7	15		A
High-side (HS) recovery threshold	$I_{RECOVERY\_HS}$	V_{IN} = 5V		-3		A
Feedback (FB) leakage	R_{FB1}	VOUT_SCALE = 1	20			kΩ
	R_{FB2}	VOUT_SCALE = 2	20			kΩ
Output discharge	R_{DIS}			120		Ω
Bootstrap (BST) Supply						
Bootstrap UVLO rising threshold	V_{BST_UVLO}				2.5	V
Bootstrap UVLO hysteresis	$V_{BST\_UVLO\_HYS}$		0.2			V
Thermal Protection						
Thermal warning rising threshold (7)	T_{TW}		125	140	155	°C
Thermal warning hysteresis	T_{TW_HYS}			20		°C
Thermal shutdown rising threshold (7)	T_{TSD}		155	170	185	°C
Thermal shutdown hysteresis	T_{TSD_HYS}			20		°C
V_{OUT} Protections						
V_{OUT} over-voltage protection (OVP) rising threshold	V_{OUT_OVP}		113	116	119	% of V_{OUT}
V_{OUT} OVP hysteresis	$V_{OUT\_OVP\_HYS}$			7		% of V_{OUT}
V_{OUT} under-voltage protection (UVP) falling threshold	V_{OUT_UVP}		70	75	80	% of V_{OUT}
V_{OUT} UVP hysteresis	$V_{OUT\_UVP\_HYS}$			7		% of V_{OUT}
Hiccup time range (9)	t_{HICCUP}		2		8	ms

ELECTRICAL CHARACTERISTICS *(continued)*

Typical values are V_{IN} = 5V, V_{EN} = 2V, T_J = 25°C, all voltages with respect to ground, unless otherwise noted. Minimum and maximum values are at V_{IN} = 5V, V_{EN} = 2V, T_J = -40°C to +150°C, all voltages with respect to ground, guaranteed by characterization, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
V_{IN} OVP						
V_{IN} OVP rising threshold	V_{IN_OVP}		6.5	6.7	6.85	V
V_{IN} OVP hysteresis	$V_{IN\_OVP\_HYS}$			0.7		V
V_{IN} OVP delay time	t_{VIN_OVP}			7		µs
Enable (EN)						
EN logic on rising threshold	$V_{EN\_LOG\_RISING}$		0.25	0.65	1	V
EN rising threshold	V_{EN_RISING}		1.1	1.2	1.3	V
EN voltage hysteresis	V_{EN_HYS}			100		mV
EN leakage	I_{EN}	V_{EN} = 3.3V			10	µA
Power Good (PG)						
PG OVP rising threshold (8) (9)	V_{PG_OVP}	PG_OV_TH = 0	103	104	105	%
		PG_OV_TH = 1	105	106	107	%
PG OVP threshold hysteresis	$V_{PG\_OVP\_HYS}$			0.8		%
PG UVP falling threshold (8) (9)	V_{PG_UVP}	PG_UV_TH = 0	95	96	97	%
		PG_UV_TH = 1	93	94	95	%
PG UVP threshold hysteresis	$V_{PG\_UVP\_HYS}$			0.8		%
PG sink capability	V_{PG}	I_{PG} = 1mA			300	mV
PG delay range (9)	t_{PG_DELAY}		0		10	ms
PG rising deglitch	$t_{PG\_R\_DEGLITCH}$			20		µs
PG falling deglitch	$t_{PG\_F\_DEGLITCH}$			20		µs
SCL/SDA input logic low	V_{IL}		0		0.4	V
SCL/SDA input logic high	V_{IH}		1.2			V
SCL/SDA output logic low	V_{OL}	I_{LOAD} = 3mA			0.4	V
SCL clock frequency (7)	f_{SCL}				1000	kHz
SCL high time (7)	t_{HIGH}		0.26			µs
SCL low time (7)	t_{LOW}		0.5			µs
Data set-up time (7)	t_{SU_DAT}		50			ns
Data hold time (7)	t_{HD_DAT}		0			µs
Set-up time for a repeated start command (7)	t_{SU_STA}		0.26			µs
Hold time for a start command (7)	t_{HD_STA}		0.26			µs
Bus free time between a start and a stop command (7)	t_{BUF}		0.5			µs
Set-up time for a stop command (7)	t_{SU_STO}		0.26			µs

ELECTRICAL CHARACTERISTICS *(continued)*

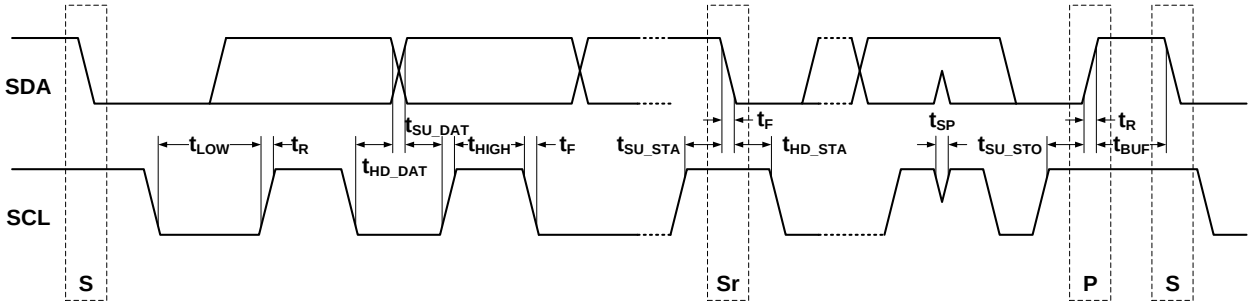
Typical values are V_{IN} = 5V, V_{EN} = 2V, T_J = 25°C, all voltages with respect to ground, unless otherwise noted. Minimum and maximum values are at V_{IN} = 5V, V_{EN} = 2V, T_J = -40°C to +150°C, all voltages with respect to ground, guaranteed by characterization, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
SCL/SDA rising time (7)	t_R				120	ns
SCL/SDA falling time (7)	t_F	V_{DD} supplies the digital interface	20 x (V_{DD} / 5.5V)		120	ns
Suppressed spike pulse width (7)	t_{SP}		0		50	ns
Capacitance bus for each bus line (7)	C_B				550	pF

Notes:

7) Derived from bench characterization. Not tested in production.
8) The PG threshold is based on the nominal V_{OUT}.
9) Use the write register to set the EC parameters. See the Register Map section starting on page 39 for a detailed description.
10) Set VOUT_SCALE to 1 when V_{OUT} is between 0.5V and 1.8V. If V_{OUT} is between 1.8V and 3.6V, set VOUT_SCALE to 2.

DIGITAL INTERFACE TIMING DIAGRAM



S: Start Command

Sr: Repeated Start Command

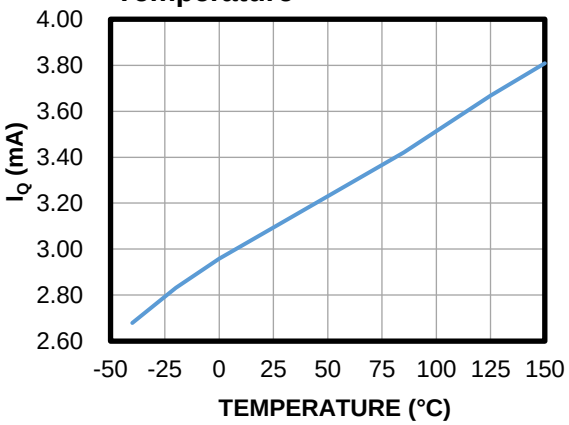
P: Stop Command

Figure 1: Digital Interface Compatible Timing Diagram

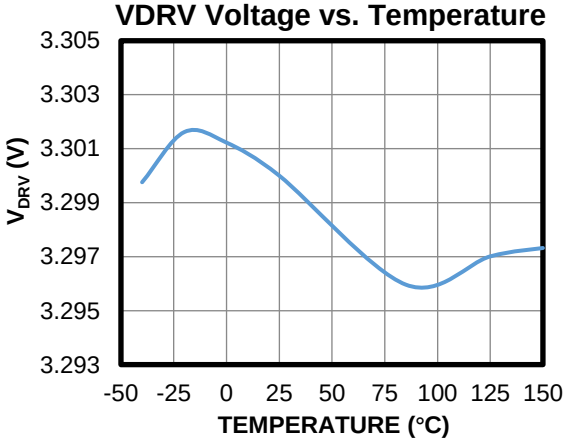
TYPICAL CHARACTERISTICS

V_{IN} = 5V, T_J = -40°C to +150°C, unless otherwise noted.

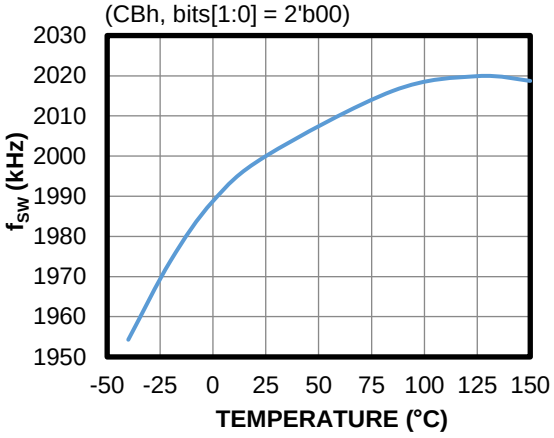
Quiescent Current vs. Temperature



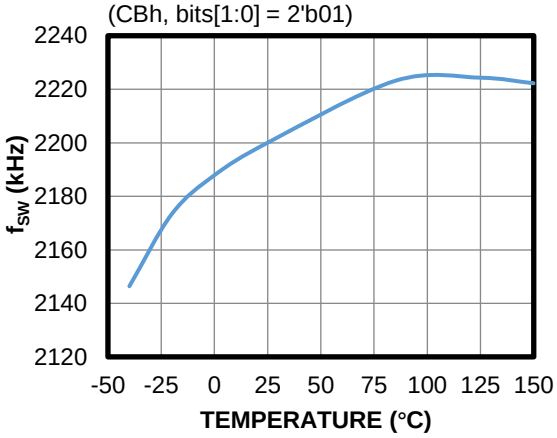
VDRV Voltage vs. Temperature



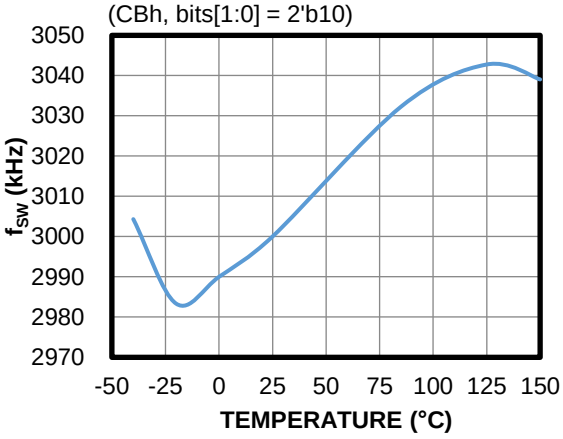
Switching Frequency vs. Temperature
(CBh, bits[1:0] = 2'b00)



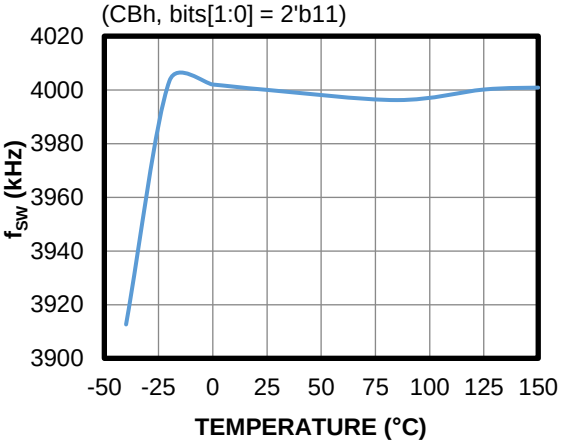
Switching Frequency vs. Temperature
(CBh, bits[1:0] = 2'b01)



Switching Frequency vs. Temperature
(CBh, bits[1:0] = 2'b10)



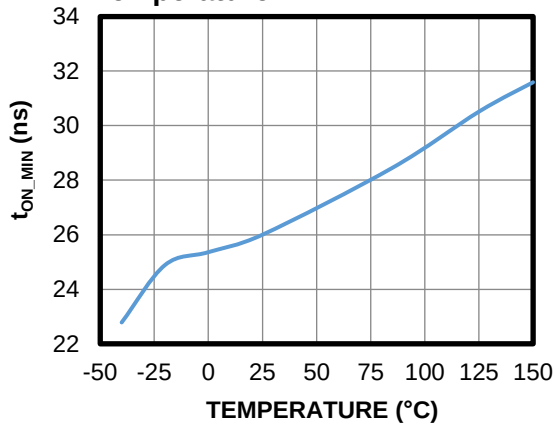
Switching Frequency vs. Temperature
(CBh, bits[1:0] = 2'b11)



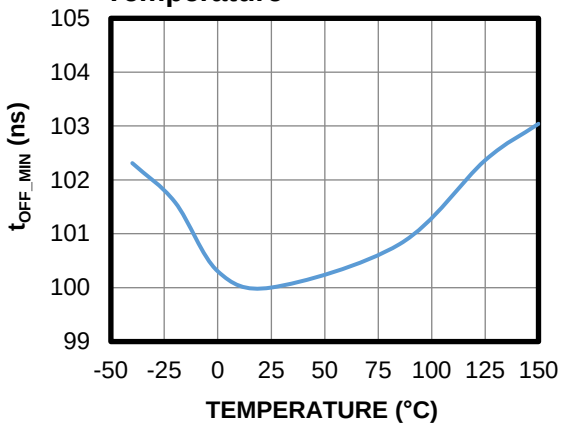
TYPICAL CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_J = -40°C to +150°C, unless otherwise noted.

Minimum On Time vs. Temperature

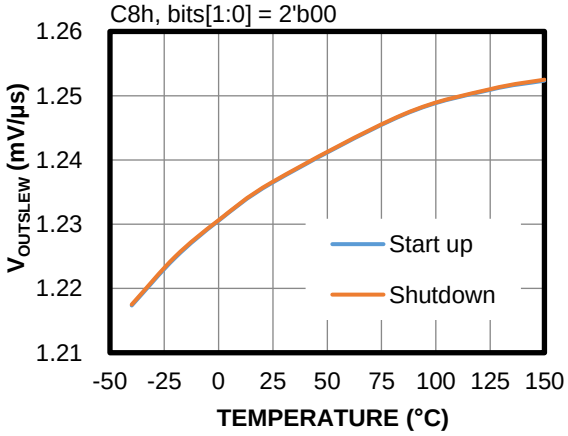


Minimum Off Time vs. Temperature



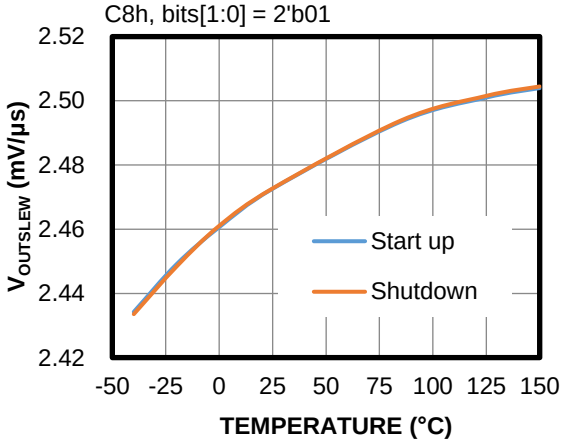
V_{OUT} Slew Rate vs. Temperature

29h, bit[0] = 1'b0; C6h, bits[1:0] = 2'b00; C8h, bits[1:0] = 2'b00



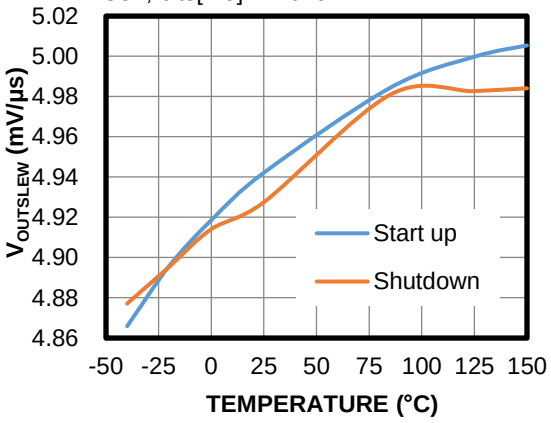
V_{OUT} Slew Rate vs. Temperature

29h, bit[0] = 1'b0; C6h, bits[1:0] = 2'b01; C8h, bits[1:0] = 2'b01



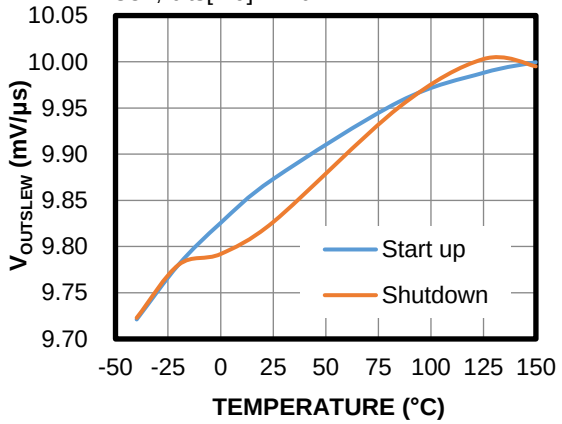
V_{OUT} Slew Rate vs. Temperature

29h, bit[0] = 1'b0; C6h, bits[1:0] = 2'b10; C8h, bits[1:0] = 2'b10



V_{OUT} Slew Rate vs. Temperature

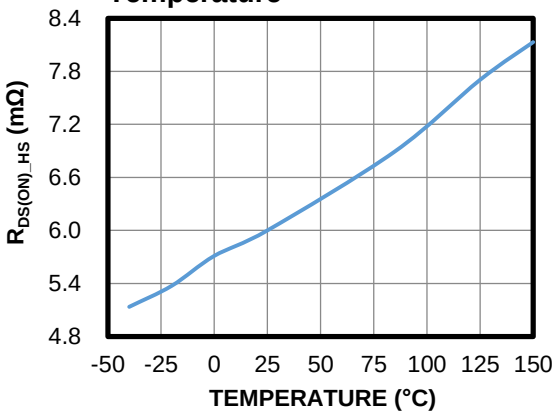
29h, bit[0] = 1'b0; C6h, bits[1:0] = 2'b11; C8h, bits[1:0] = 2'b11



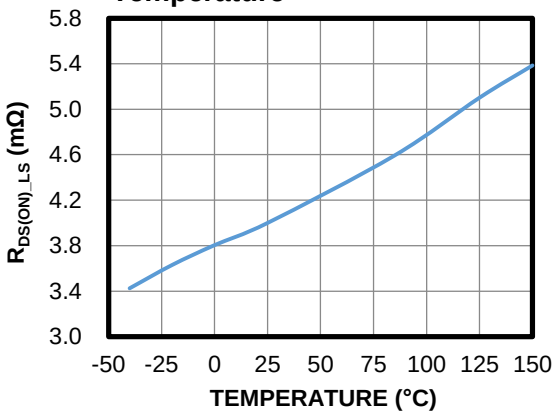
TYPICAL CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_J = -40°C to +150°C, unless otherwise noted.

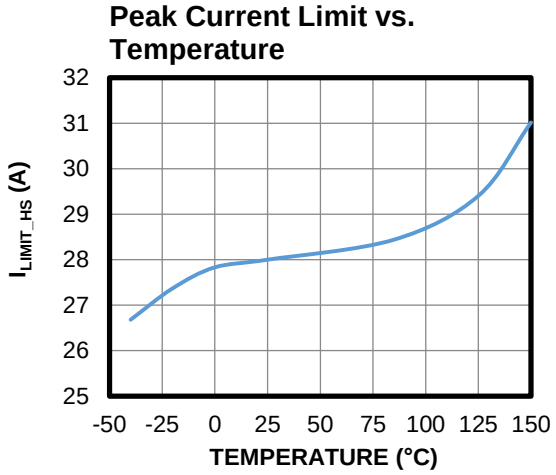
HS-FET On Resistance vs. Temperature



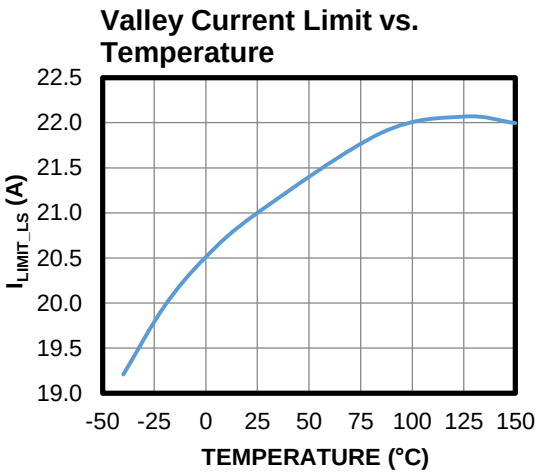
LS-FET On Resistance vs. Temperature



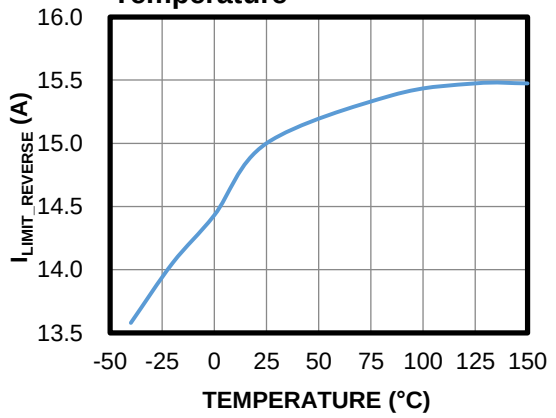
Peak Current Limit vs. Temperature



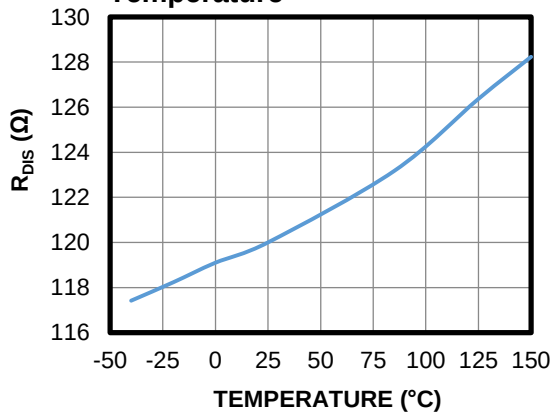
Valley Current Limit vs. Temperature



Reverse Current Limit vs. Temperature



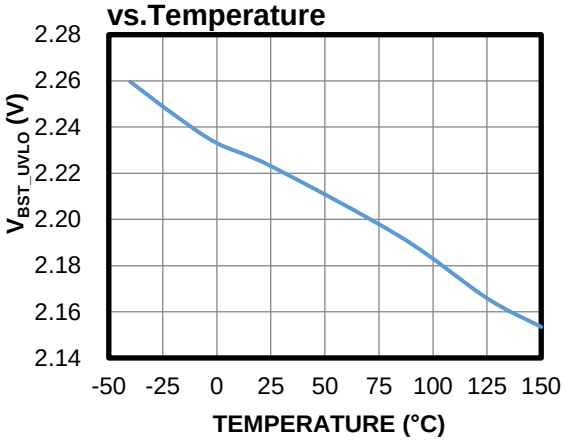
Output Discharge vs. Temperature



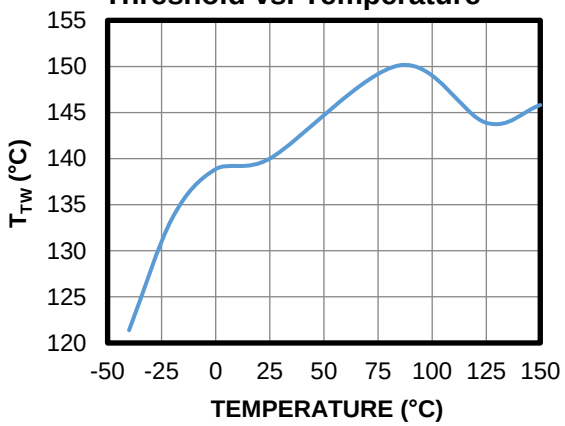
TYPICAL CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_J = -40°C to +150°C, unless otherwise noted.

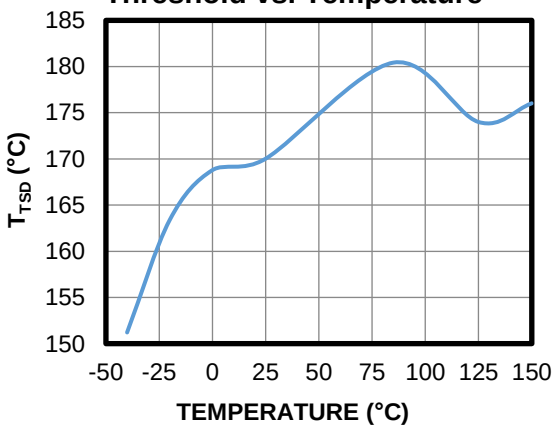
BST UVLO Rising Threshold vs.Temperature



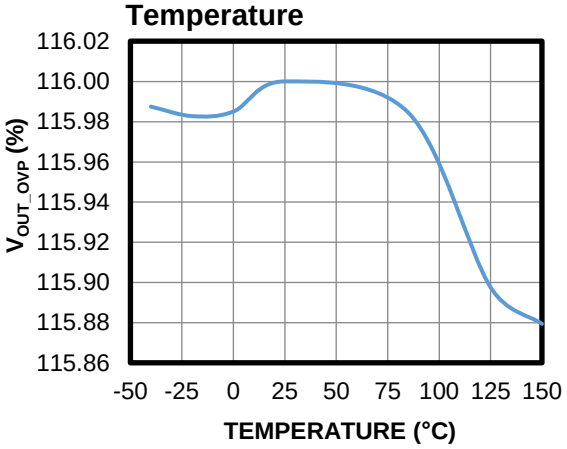
Thermal Warning Rising Threshold vs. Temperature



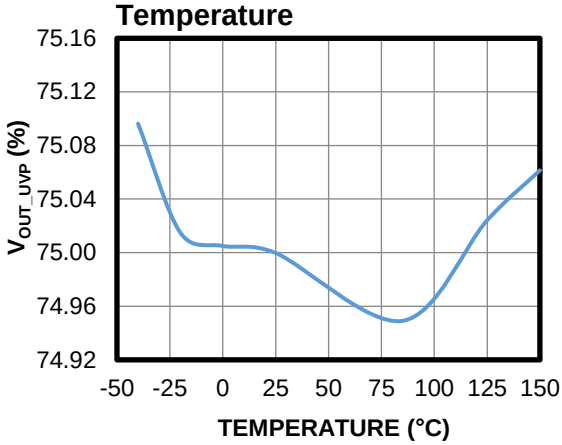
Thermal Shutdown Rising Threshold vs. Temperature



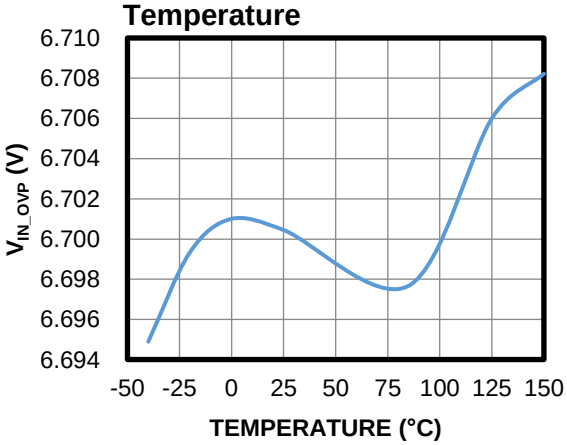
V_{OUT} OVP Rising Threshold vs. Temperature



V_{OUT} UVP Faling Threshold vs. Temperature



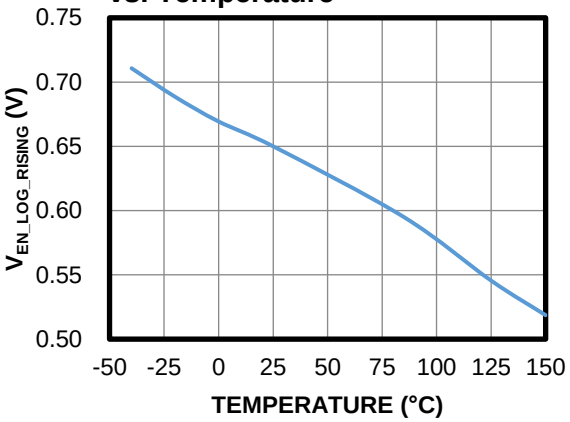
V_{IN} OVP Rising Threshold vs. Temperature



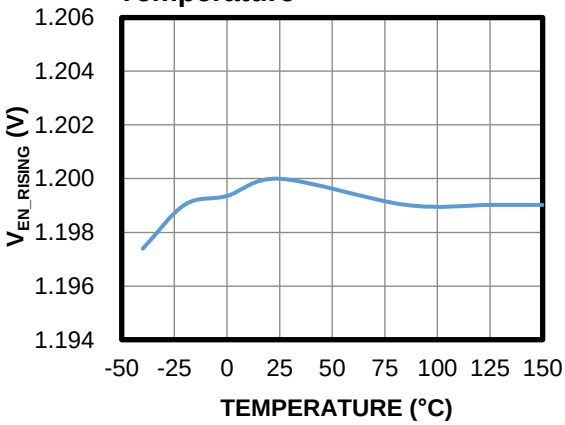
TYPICAL CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_J = -40°C to +150°C, unless otherwise noted.

EN Login On Rising Threshold vs. Temperature



V_{EN} Rising Threshold vs. Temperature

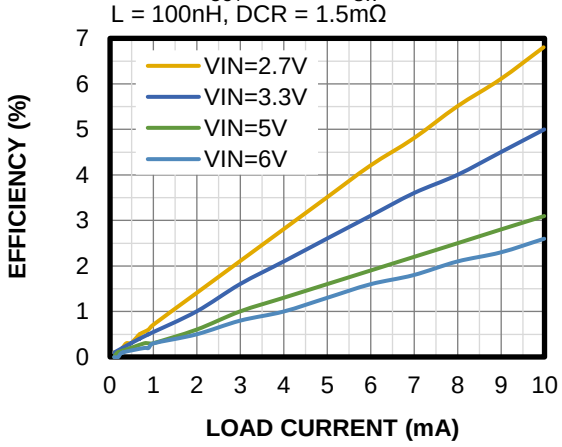


TYPICAL PERFORMANCE CHARACTERISTICS

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

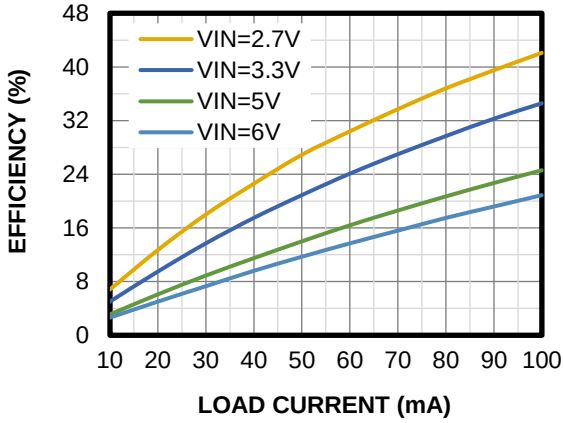
Efficiency vs. Load Current

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz, L = 100nH, DCR = 1.5mΩ



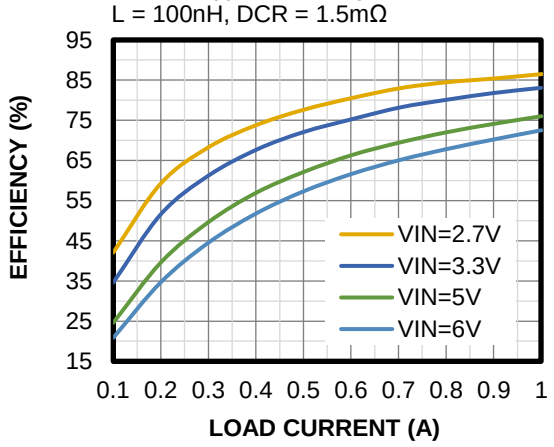
Efficiency vs. Load Current

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz, L = 100nH, DCR = 1.5mΩ



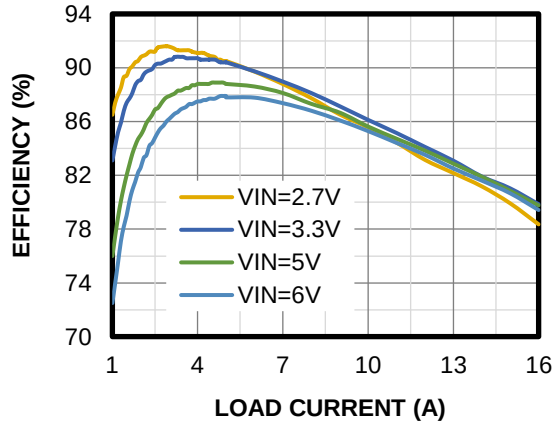
Efficiency vs. Load Current

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz, L = 100nH, DCR = 1.5mΩ



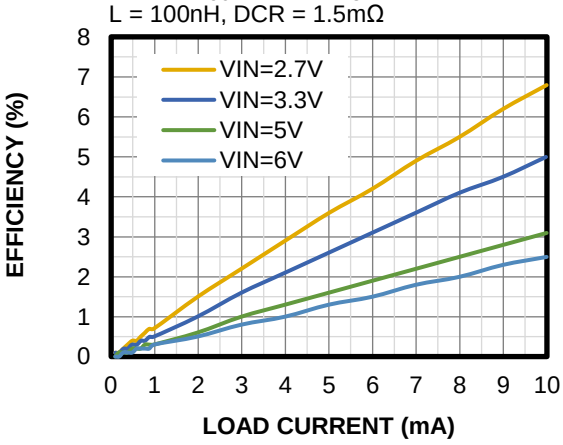
Efficiency vs. Load Current

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz, L = 100nH, DCR = 1.5mΩ



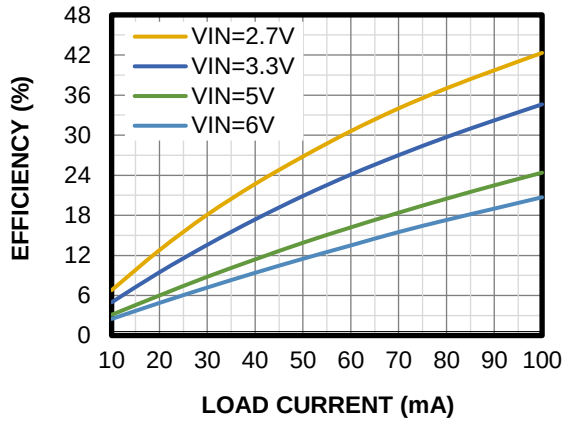
Efficiency vs. Load Current

FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



Efficiency vs. Load Current

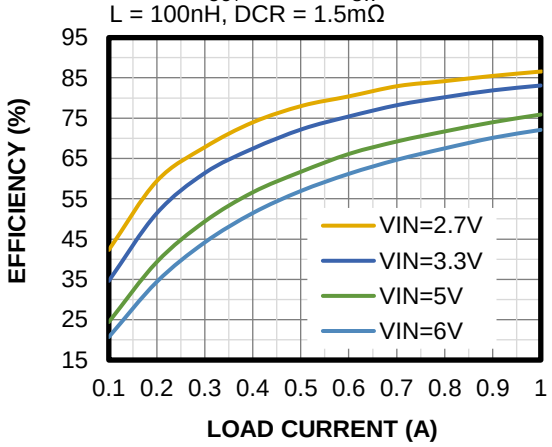
FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



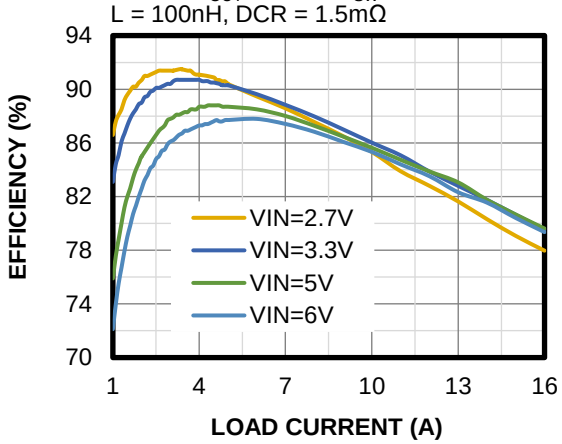
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

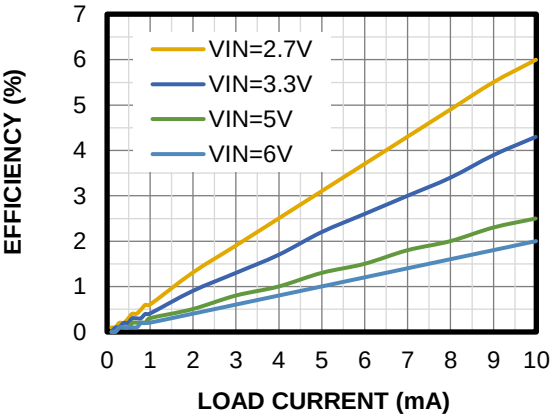
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



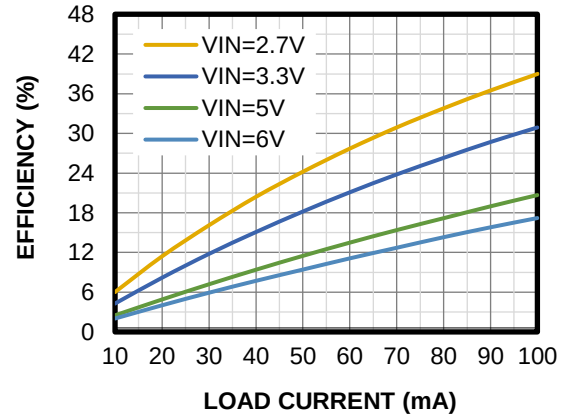
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



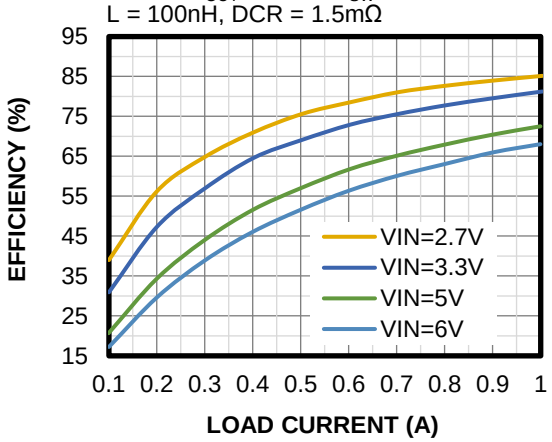
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



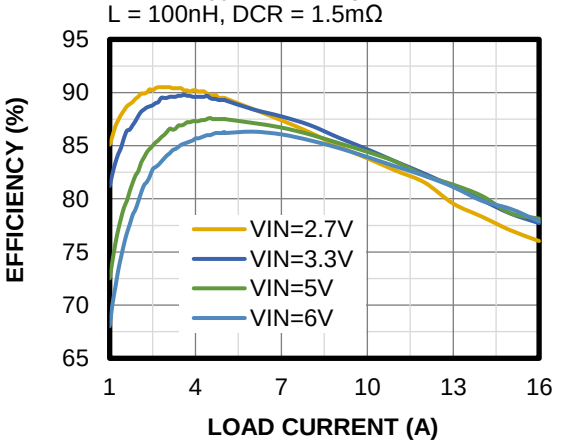
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



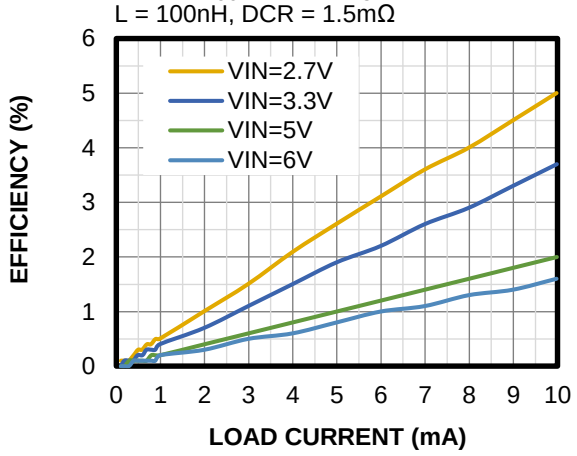
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



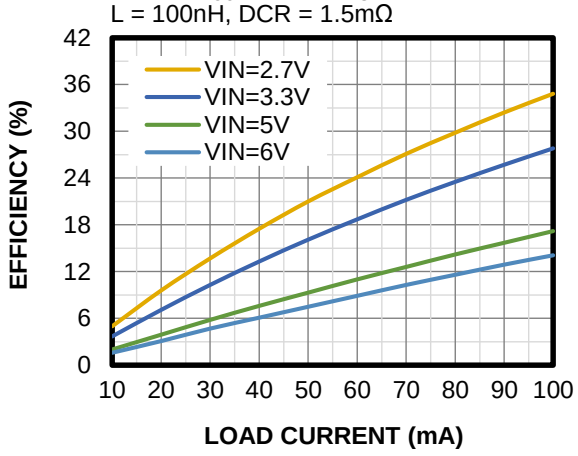
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

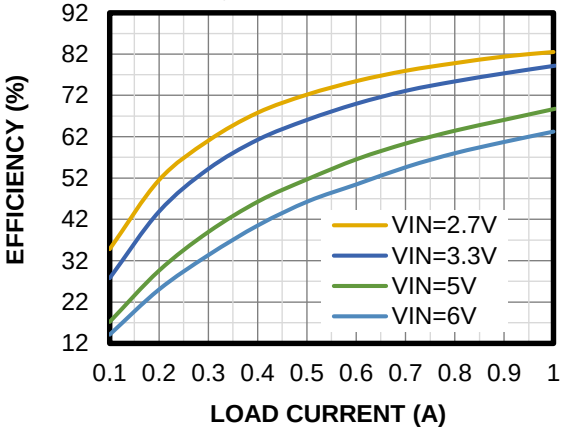
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ



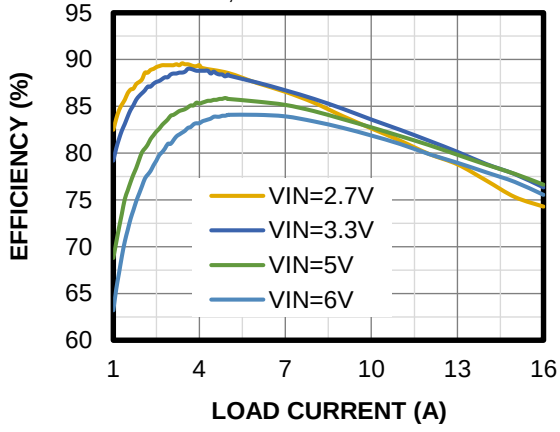
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ



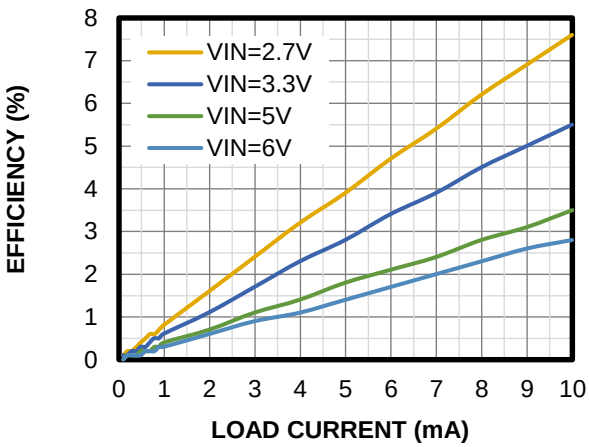
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ



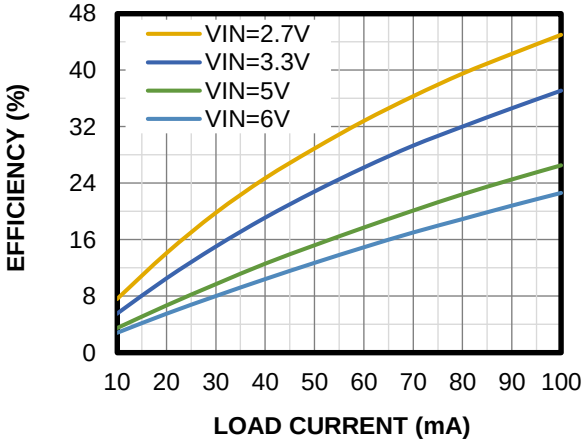
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ



Efficiency vs. Load Current
FCCM, V_{OUT} = 0.9V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



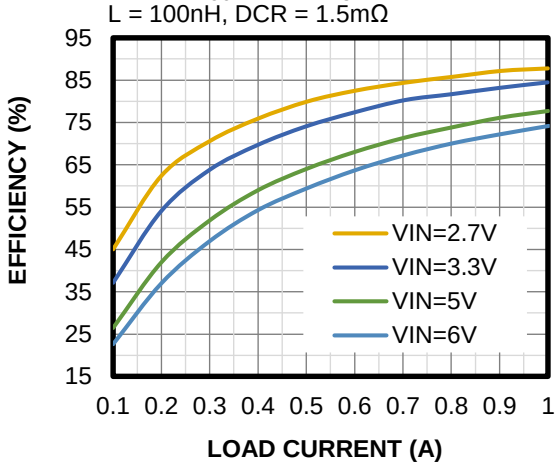
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.9V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



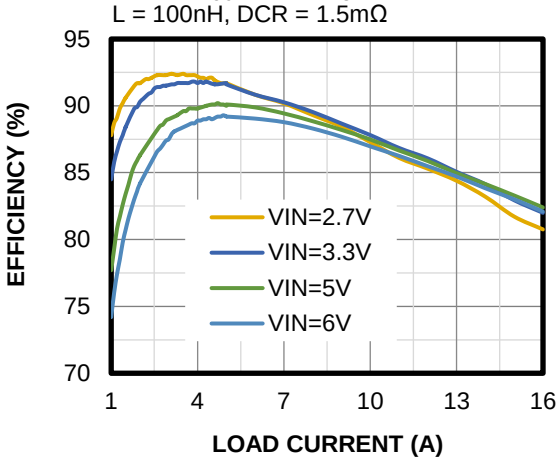
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

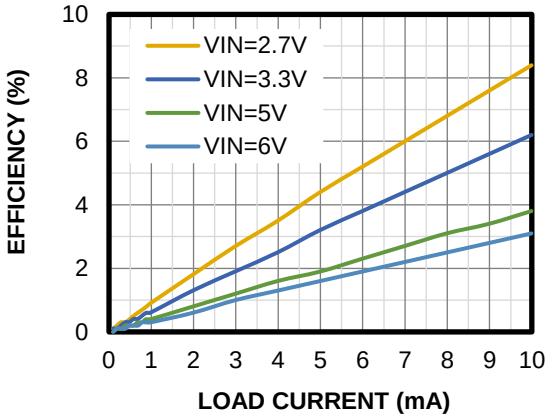
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.9V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



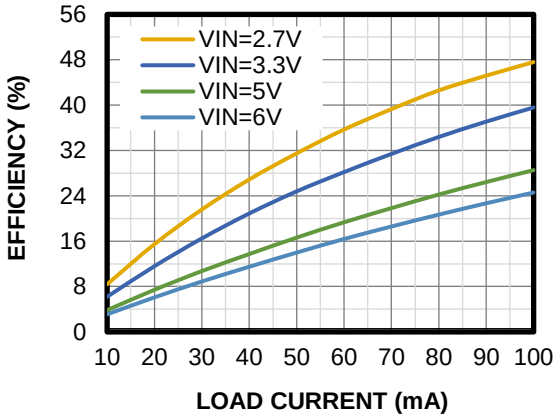
Efficiency vs. Load Current
FCCM, V_{OUT} = 0.9V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



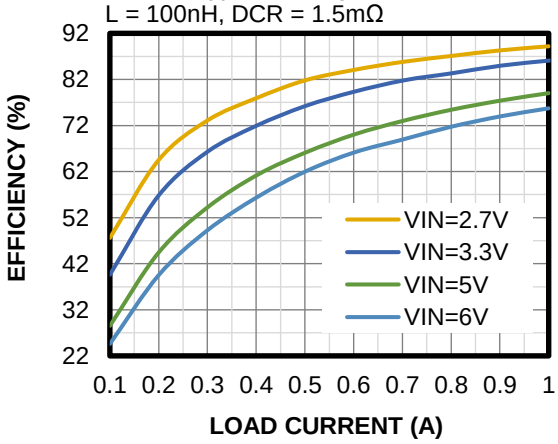
Efficiency vs. Load Current
FCCM, V_{OUT} = 1.1V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



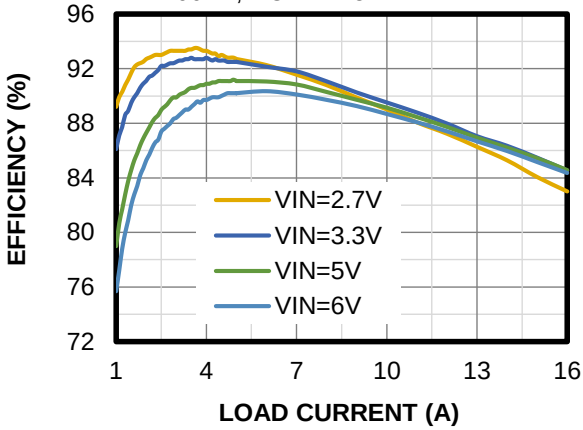
Efficiency vs. Load Current
FCCM, V_{OUT} = 1.1V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



Efficiency vs. Load Current
FCCM, V_{OUT} = 1.1V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



Efficiency vs. Load Current
FCCM, V_{OUT} = 1.1V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ

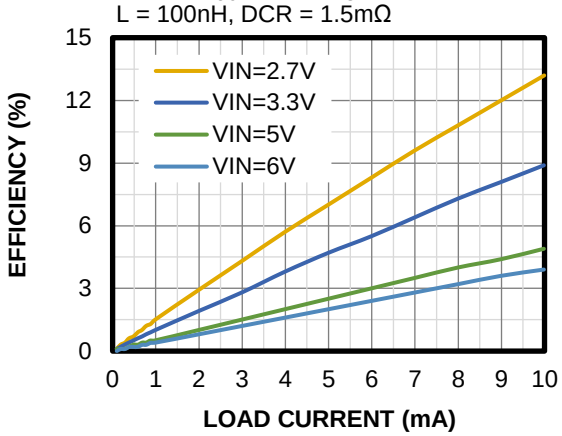


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

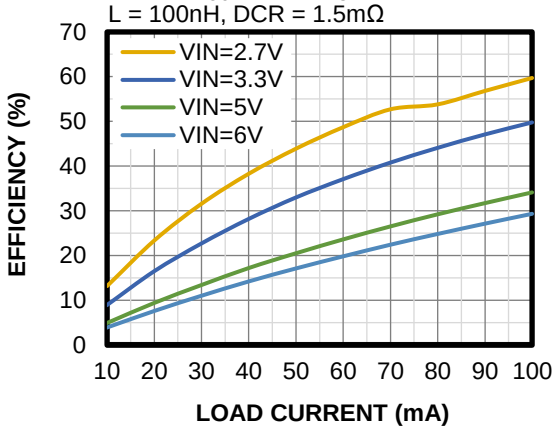
Efficiency vs. Load Current

FCCM, V_{OUT} = 1.8V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



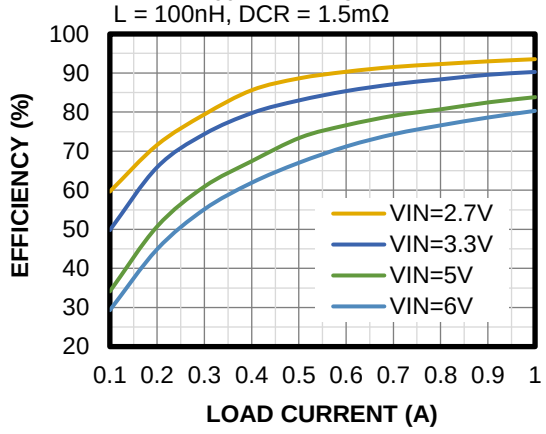
Efficiency vs. Load Current

FCCM, V_{OUT} = 1.8V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



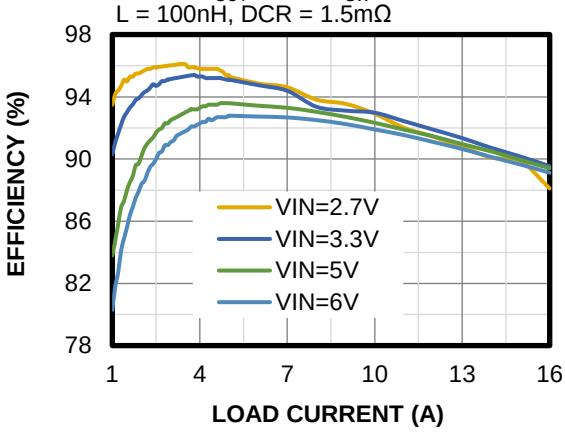
Efficiency vs. Load Current

FCCM, V_{OUT} = 1.8V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



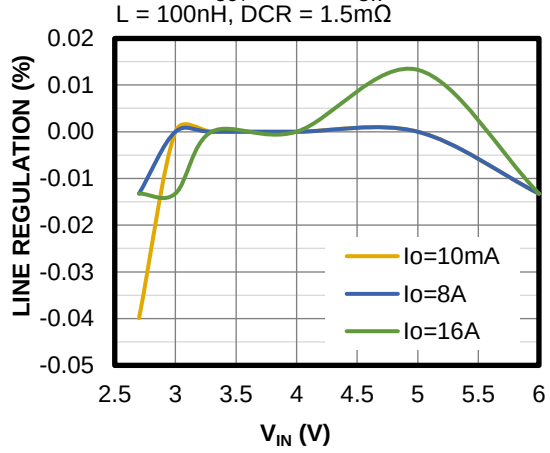
Efficiency vs. Load Current

FCCM, V_{OUT} = 1.8V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ



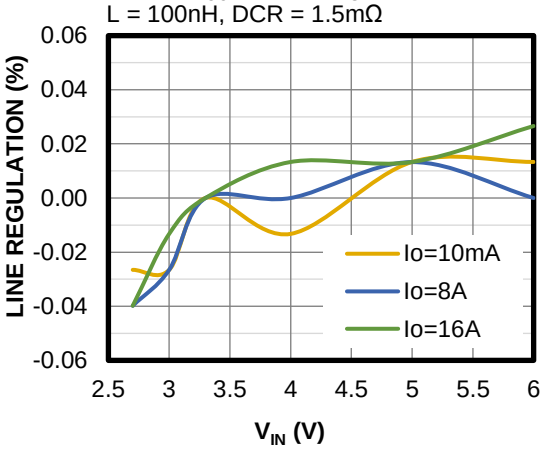
Line Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz, L = 100nH, DCR = 1.5mΩ



Line Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz, L = 100nH, DCR = 1.5mΩ

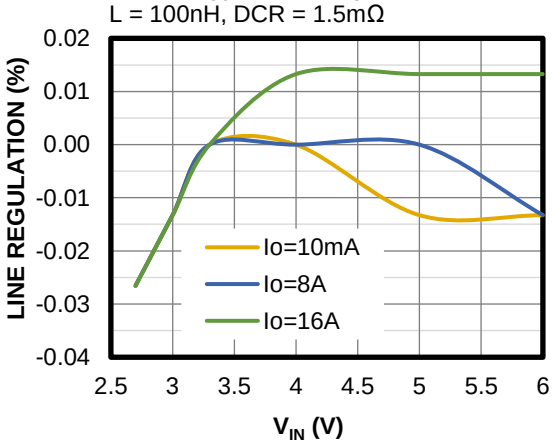


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

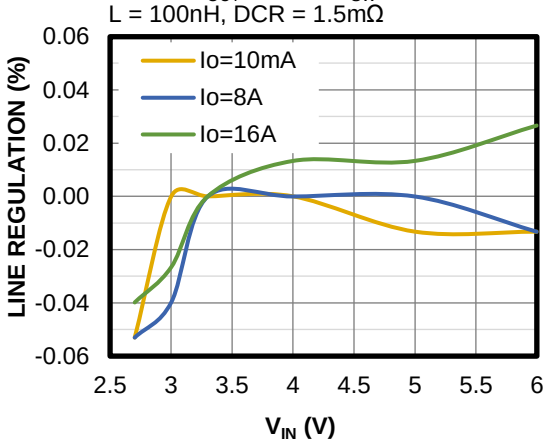
Line Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



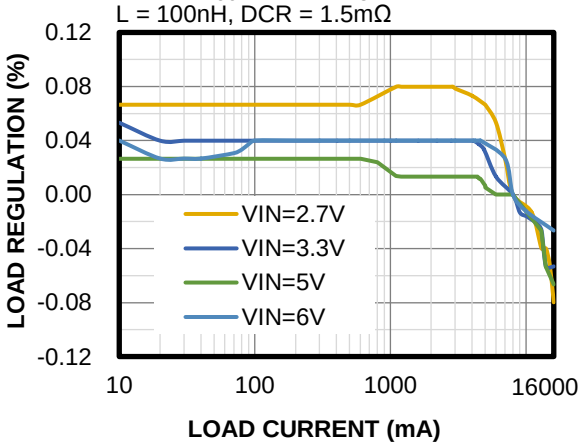
Line Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ



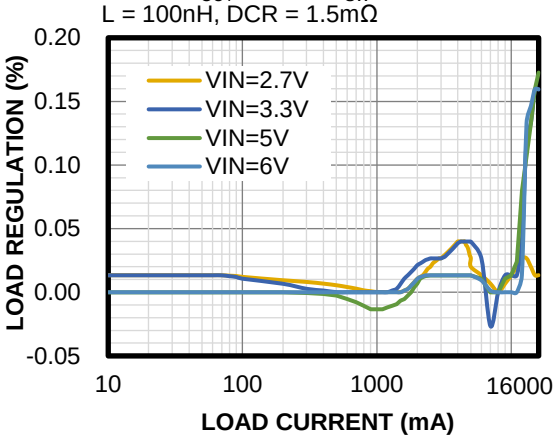
Load Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz,
L = 100nH, DCR = 1.5mΩ



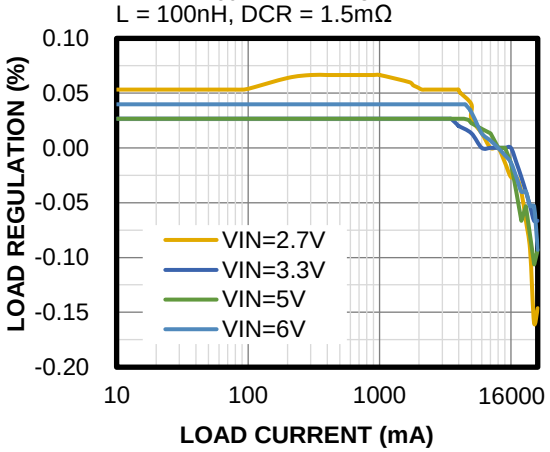
Load Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



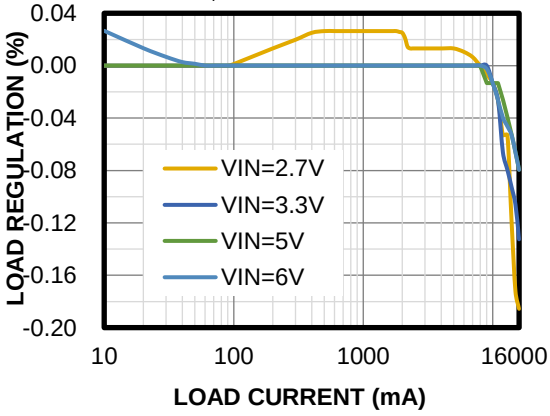
Load Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



Load Regulation

FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ

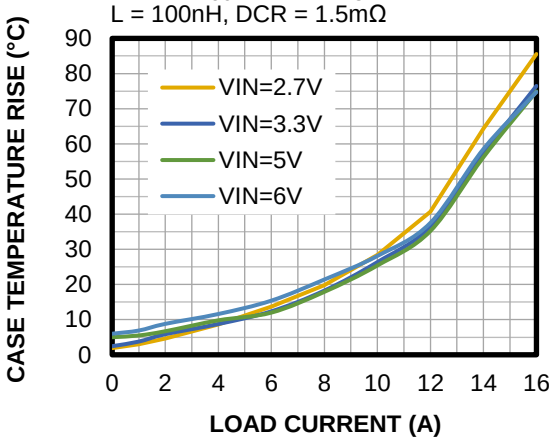


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

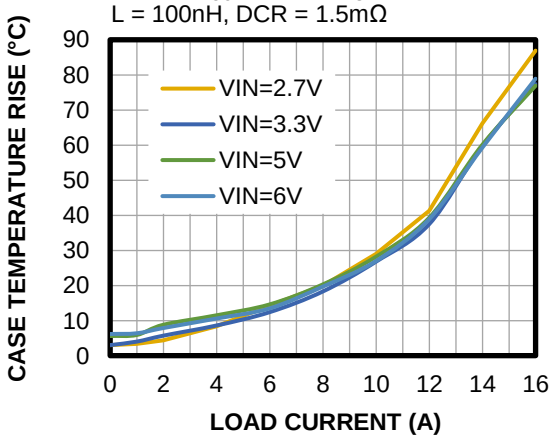
Case Temperature Rise

FCCM, V_{OUT} = 0.75V, f_{SW} = 2MHz,
L = 100nH, DCR = 1.5mΩ



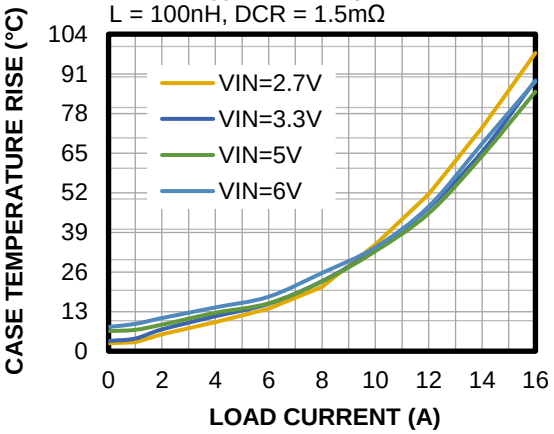
Case Temperature Rise

FCCM, V_{OUT} = 0.75V, f_{SW} = 2.2MHz,
L = 100nH, DCR = 1.5mΩ



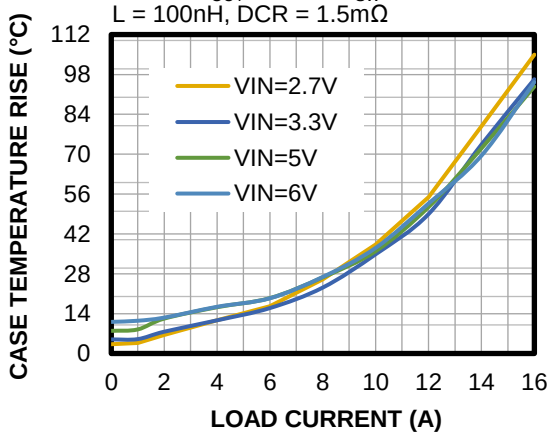
Case Temperature Rise

FCCM, V_{OUT} = 0.75V, f_{SW} = 3MHz,
L = 100nH, DCR = 1.5mΩ



Case Temperature Rise

FCCM, V_{OUT} = 0.75V, f_{SW} = 4MHz,
L = 100nH, DCR = 1.5mΩ

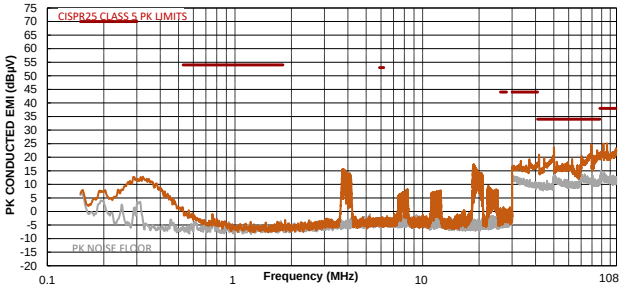


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 6V, V_{OUT} = 1.1V, L= 100nH (11)**, C_{OUT} = 4 x 47µF, f_{SW} = 4MHz, I_{OUT} = 16A, T_A = 25°C, unless otherwise noted.** (12)

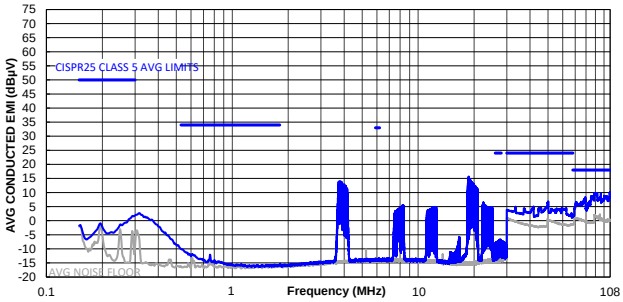
CISPR 25 Class 5 Peak Conducted Emissions

150kHz to 108MHz



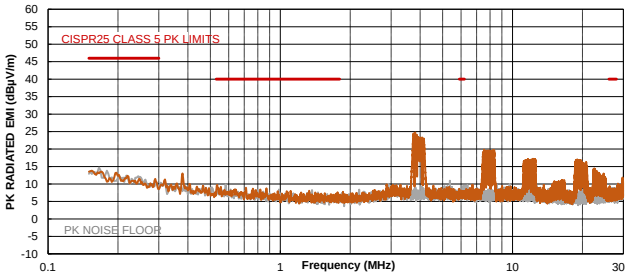
CISPR 25 Class 5 Average Conducted Emissions

150kHz to 108MHz



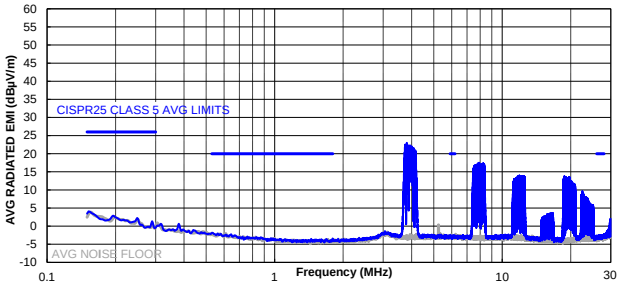
CISPR 25 Class 5 Peak Radiated Emissions

150kHz to 30MHz



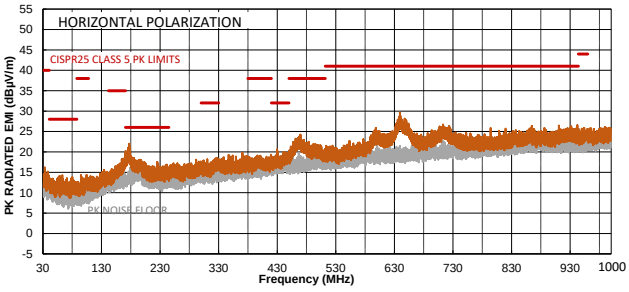
CISPR 25 Class 5 Average Radiated Emissions

150kHz to 30MHz



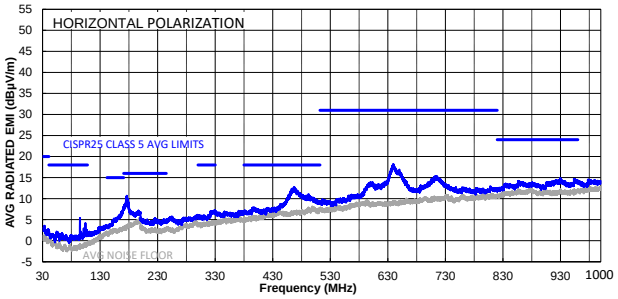
CISPR 25 Class 5 Peak Radiated Emissions

Horizontal, 30MHz to 1GHz



CISPR 25 Class 5 Average Radiated Emissions

Horizontal, 30MHz to 1GHz

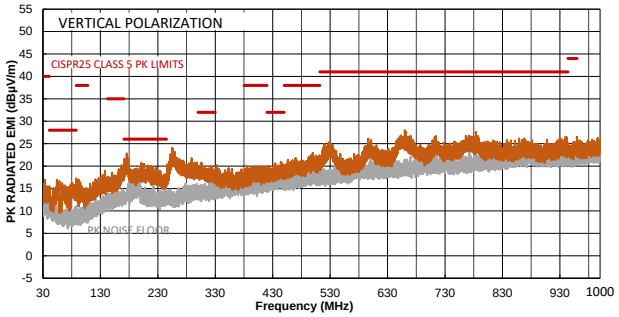


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 6V, V_{OUT} = 1.1V, L= 100nH (11), C_{OUT} = 4 x 47µF, f_{SW} = 4MHz, I_{OUT} = 16A, T_A = 25°C, unless otherwise noted. (12)

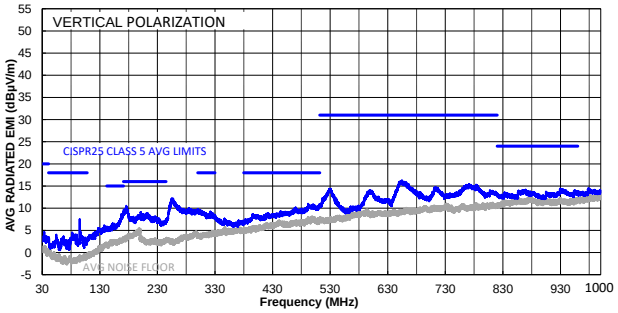
CISPR 25 Class 5 Peak Radiated Emissions

Vertical, 30MHz to 1GHz



CISPR 25 Class 5 Average Radiated Emissions

Vertical, 30MHz to 1GHz



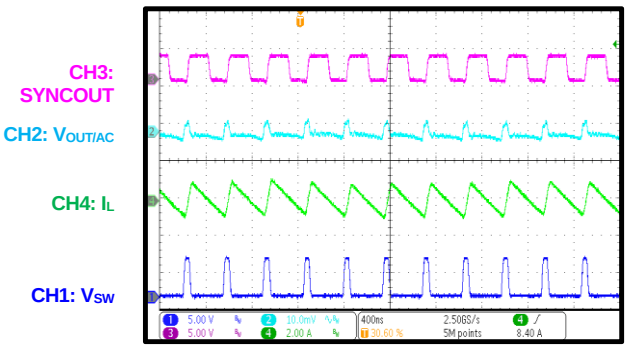
Notes:

11) Inductor part number: HBED042T-R10MS-99; DCR = 1.3mΩ.
12) The EMC test results are based on the typical application circuit with EMI filters (see Figure 14 on page 58).

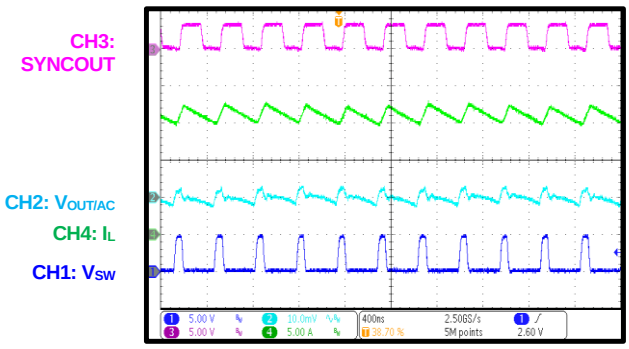
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

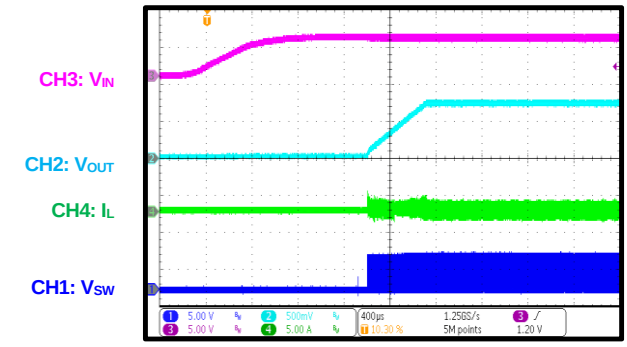
Steady State
I_{OUT} = 0A



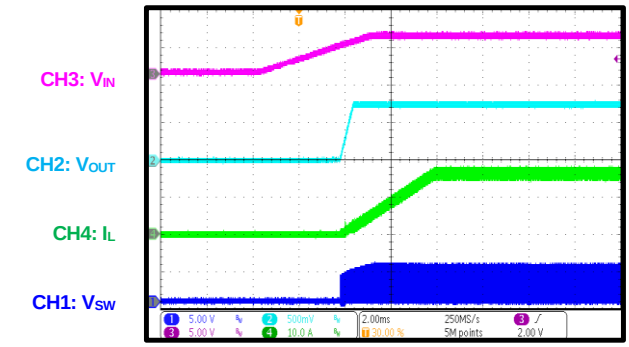
Steady State
I_{OUT} = 16A



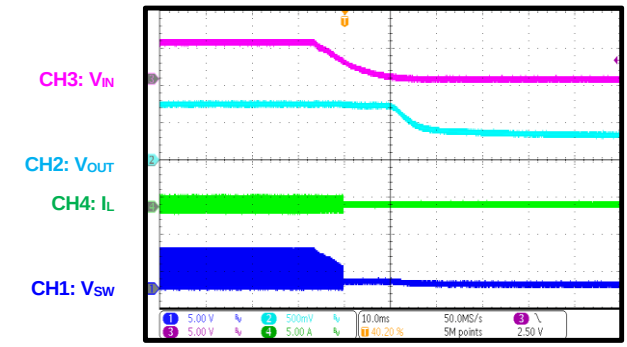
Start-Up through VIN
I_{OUT} = 0A



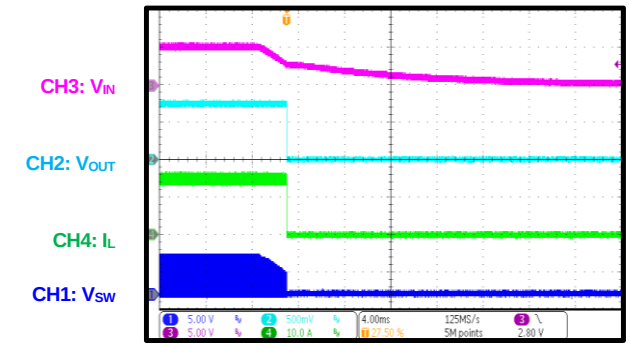
Start-Up through VIN
I_{OUT} = 16A



Shutdown through VIN
I_{OUT} = 0A



Shutdown through VIN
I_{OUT} = 16A

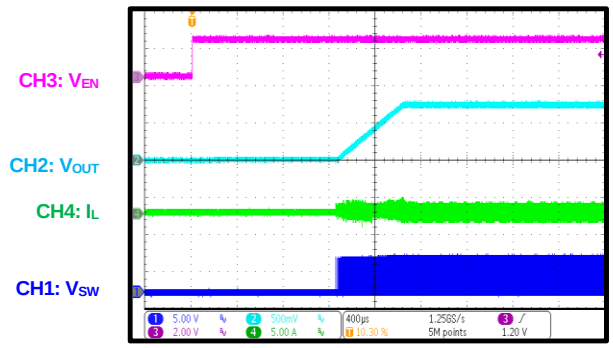


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

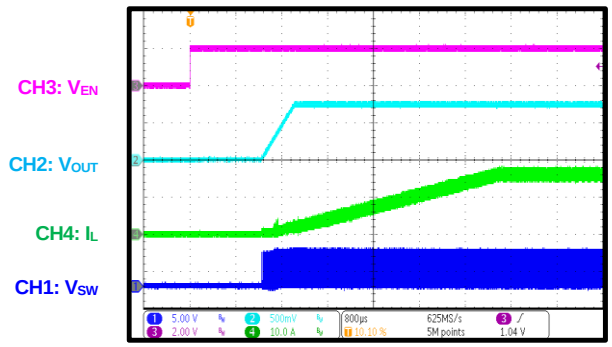
Start-Up through EN

I_{OUT} = 0A



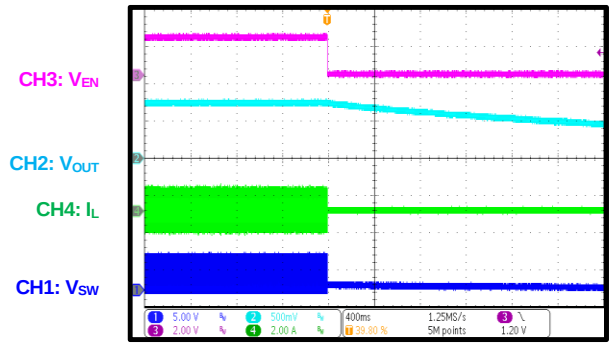
Start-Up through EN

I_{OUT} = 16A



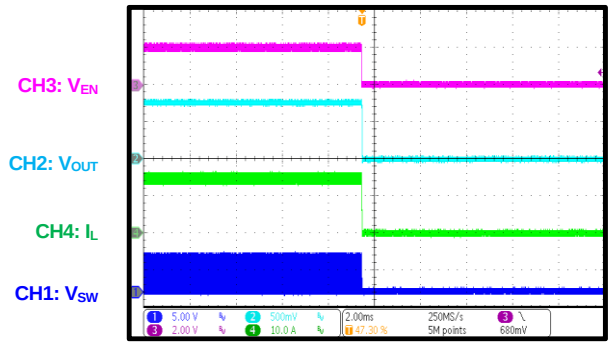
Shutdown through EN

I_{OUT} = 0A



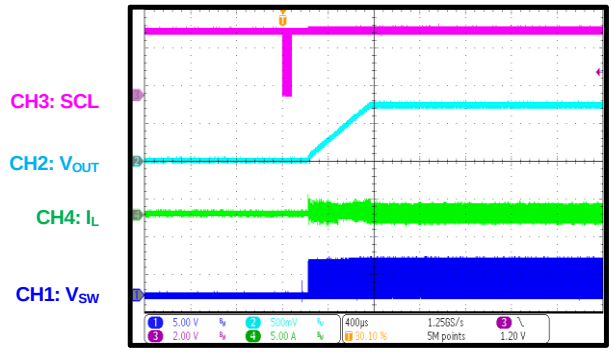
Shutdown through EN

I_{OUT} = 16A



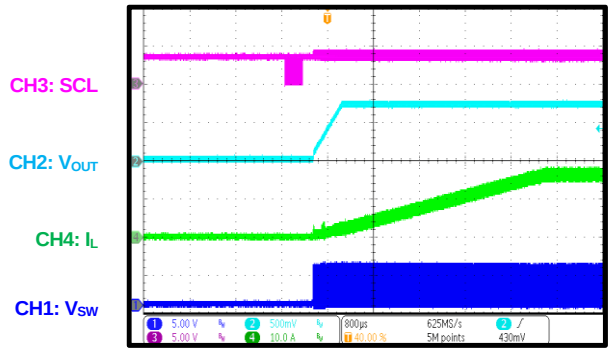
Start-Up via the Digital Interface

I_{OUT} = 0A



Start-Up via the Digital Interface

I_{OUT} = 16A

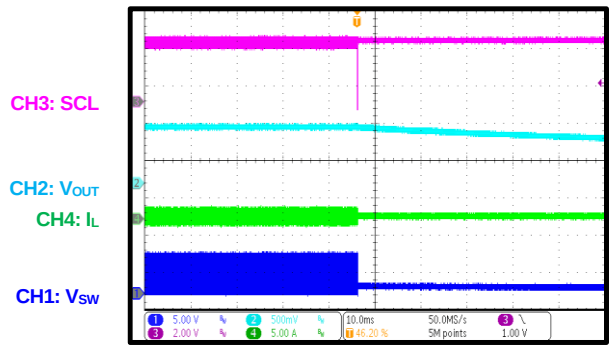


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

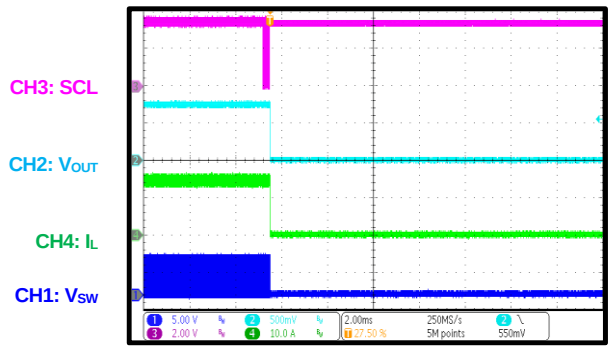
Shutdown via the Digital Interface

I_{OUT} = 0A



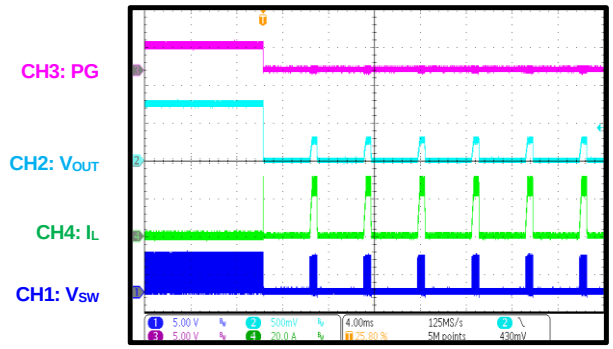
Shutdown via the Digital Interface

I_{OUT} = 16A



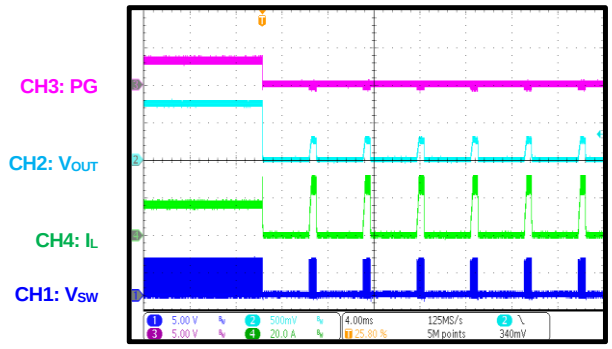
SCP Entry

I_{OUT} = 0A



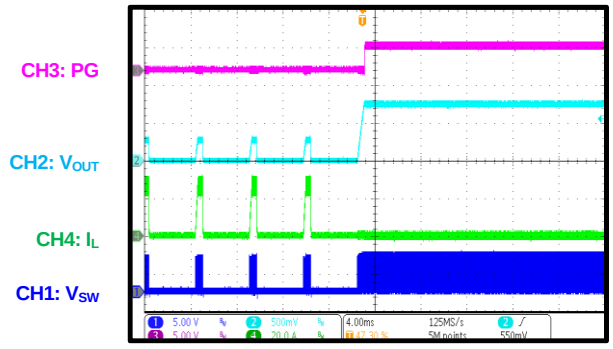
SCP Entry

I_{OUT} = 16A



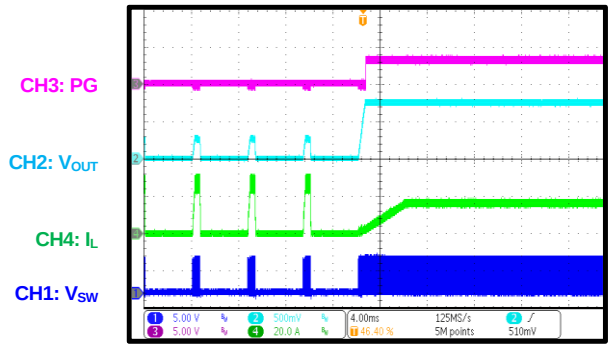
SCP Recovery

I_{OUT} = 0A



SCP Recovery

I_{OUT} = 16A

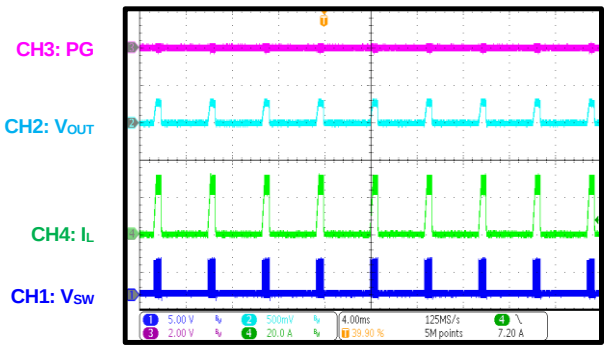


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

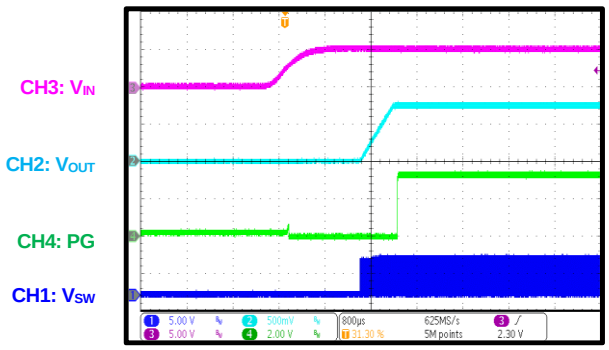
SCP Steady State

I_{OUT} = 0A



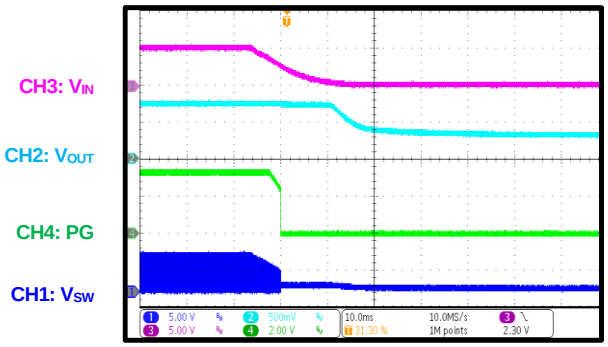
PG during Start-Up through VIN

I_{OUT} = 0A



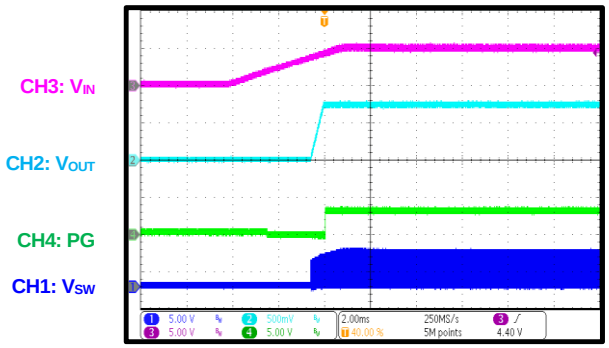
PG during Shutdown through VIN

I_{OUT} = 0A



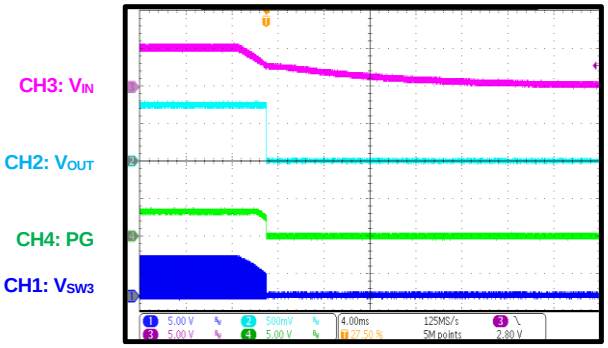
PG during Start-Up through VIN

I_{OUT} = 16A



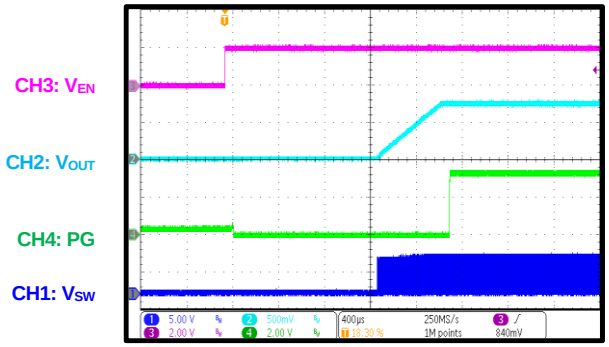
PG during Shutdown through VIN

I_{OUT} = 16A



PG during Start-Up through EN

I_{OUT} = 0A

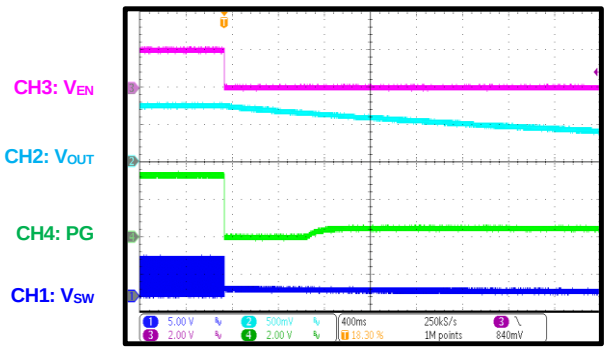


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

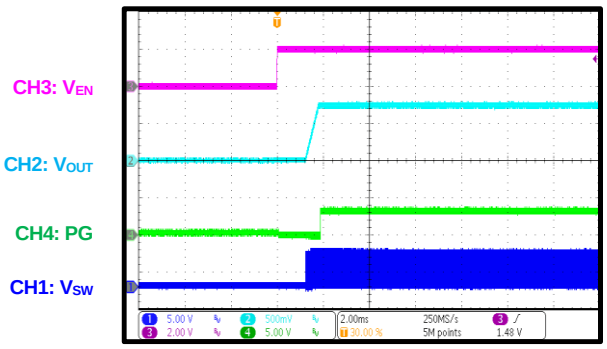
PG during Shutdown through EN

I_{OUT} = 0A



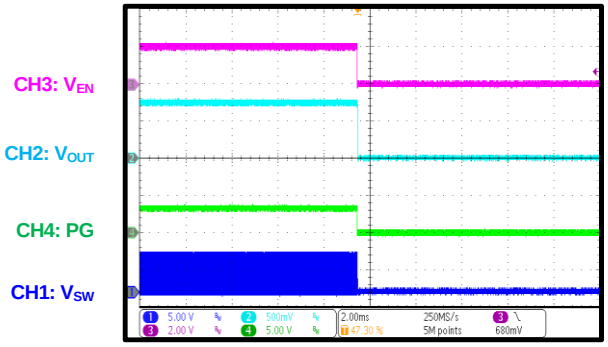
PG during Start-Up through EN

I_{OUT} = 16A



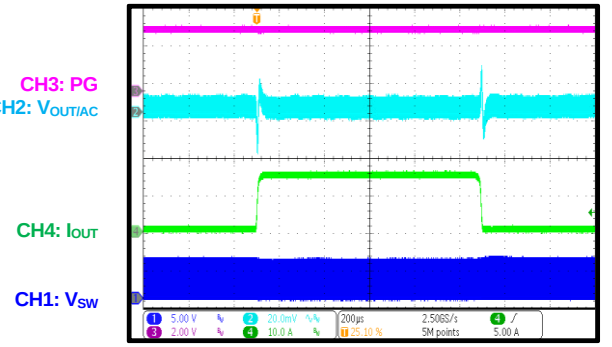
PG during Shutdown through EN

I_{OUT} = 16A



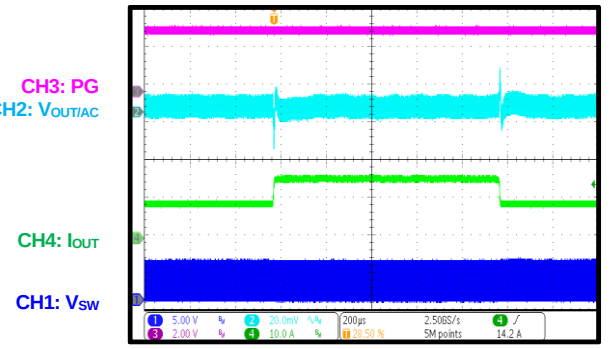
Load Transient Response

I_{OUT} = 0A to 16A, 1.6A/µs



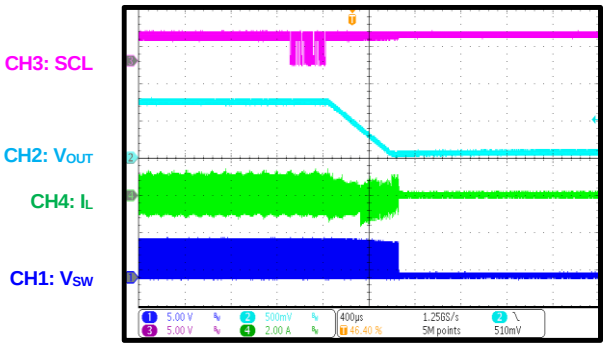
Load Transient Response

I_{OUT} = 8A to 16A, 1.6A/µs



Soft Shutdown via the Digital Interface

I_{OUT} = 0A

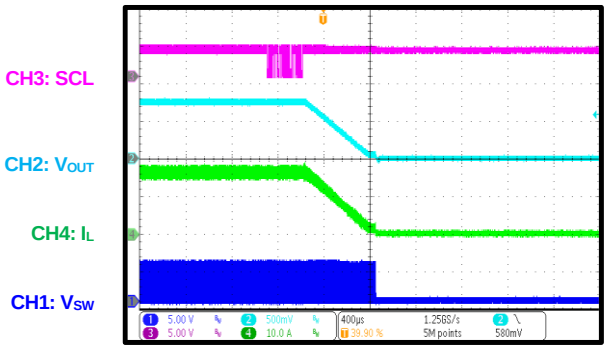


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{OUT} = 0.75V, L = 100nH, C_{OUT} = 4 x 47µF, f_{SW} = 3MHz, T_A = 25°C, unless otherwise noted.

Soft Shutdown via the Digital Interface

I_{OUT} = 16A



FUNCTIONAL BLOCK DIAGRAM

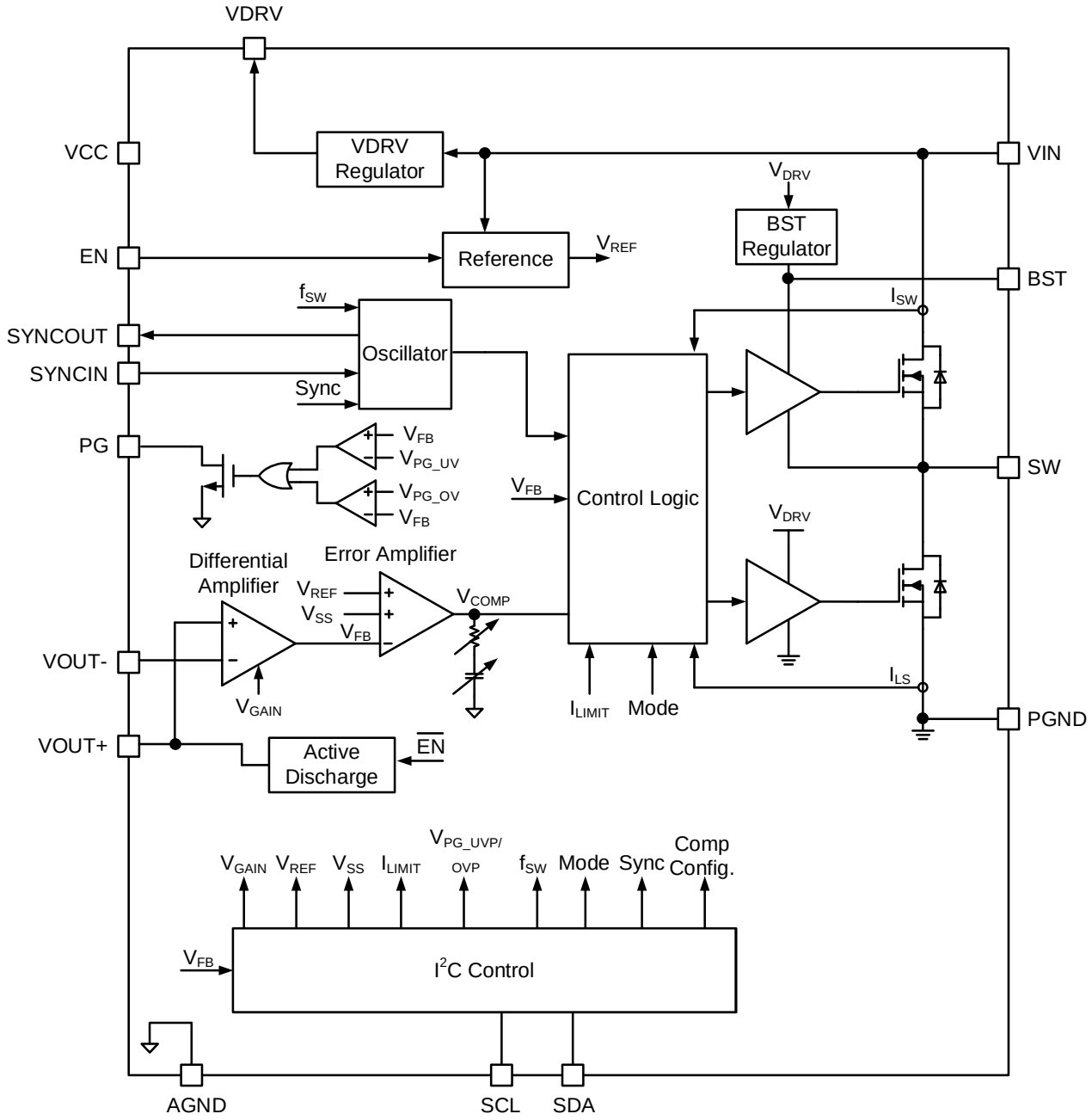


Figure 2: Functional Block Diagram

OPERATION

The MPQ2288 is a high-efficiency, high-frequency, synchronous buck regulator with integrated internal high-side and low side-power MOSFETs (HS-FET and LS-FET, respectively). The device provides up to 16A of highly efficient output current (I_{OUT}) with fixed-frequency zero-delay pulse-width modulation (PWM) (ZDP™) control.

The device features a configurable 2MHz to 4MHz switching frequency (f_{SW}), soft start (SS), soft shutdown , and precision current limit (I_{LIMIT}). It also features a digital interface with packet error checking (PEC) and an integrated, multi-page one-time programmable (OTP) memory, which allows for a high degree of configurability.

Zero-Delay PWM (ZDP™) Control

Automotive applications typically require fixed-frequency operation to reduce EMI; however, traditional fixed-control topologies have major limitations. Voltage-mode control is difficult to compensate for in automotive environments, while peak current-mode control struggles to keep up with stringent, modern system-on-chip (SoC) transient requirements with excessive output capacitances (C_{OUT}). With these requirements in mind, the MPQ2288 implements fixed-frequency ZDP™ control.

ZDP™ control combines current information with hysteretic-style output voltage (V_{OUT}) control in a clocked system. This provides near-optimal transient response while maintaining a high phase margin across a wide variety of operating conditions and external component values. In addition, it significantly reduces EMI for superior performance. The improved transient response decreases C_{OUT} requirements, which lowers system cost. Trailing edge modulation facilitates a narrow on time (t_{ON}) for high conversion ratio applications.

At the beginning of the PWM cycle, the HS-FET turns off and the LS-FET turns on immediately until the control signal reaches the COMP voltage (V_{COMP}). The HS-FET remains off for at least 80ns at the beginning of the cycle.

Light-Load Operation

Under light-load conditions, the MPQ2288 works in forced continuous conduction mode (FCCM). During FCCM, the MPQ2288 works with a fixed frequency across the no-load to full-load range. The advantages of FCCM are the constant frequency and lower V_{OUT} ripple (ΔV_{OUT}) at light loads.

The MPQ2288 has a reverse I_{LIMIT} ($I_{LIMIT\_REVERSE}$) to prevent the negative current from dropping too low and damaging the components. Once the negative inductor current (I_L) reaches $I_{LIMIT\_REVERSE}$, the LS-FET turns off and the HS-FET turns on until I_L reaches the high-side recovery threshold ($I_{RECOVERY\_HS}$).

Internal Regulators (VDRV and VCC)

The internal 3.3V VDRV regulator powers the gate driver and bootstrap (BST) supply. This regulator uses the VIN pin as its input and operates across the entire input voltage (V_{IN}) range. When V_{IN} exceeds 3.3V, VDRV is in full regulation. When V_{IN} is below 3.3V, the VDRV output (V_{DRV}) degrades. Decouple VDRV using a 4.7µF capacitor connected between VRDRV and PGND, placed as close to the VDRV pin as possible.

Connect the VDRV supply to the VCC pin using a 2.2Ω resistor. Decouple the VCC pin using a 2.2µF capacitor connected to AGND to provide power to the rest of the MPQ2288.

Dynamic Voltage Scaling

V_{OUT} can be adjusted via the digital interface during normal operation. When the voltage changes, the slope is determined by the digital interface's VOUT_SLEW register. During the rising transition, the device maintains the previous mode. During the falling transition, the device automatically switches to FCCM.

Bootstrap (BST) Charging

The BST capacitor (C_{BST}) is charged and regulated to about 3.3V by the dedicated internal BST regulator. When the voltage between the BST and SW pins is below its regulated value (2.75V), a transistor connected from VDRV to BST turns on to charge C_{BST}.

When the HS-FET is on, the BST voltage (V_{BST}) exceeds the VDRV voltage (V_{DRV}), and C_{BST} cannot be charged. At higher duty cycles, the time available to charge C_{BST} is shorter, which means C_{BST} may not be sufficiently charged.

In this scenario, the BST refresh circuit turns off the HS-FET and turns on the LS-FET to ensure that C_{BST} is sufficiently charged.

Enable (EN) Control

EN is a digital control pin that turns the converter on and off. Pull the EN pin above the specified threshold (1.2V) to turn the converter on; pull EN below 1.1V to turn it off.

SYNCIN

f_{SW} can be synchronized to the rising edge of an external clock signal applied at SYNCIN. The high amplitude of the synchronous (SYNC) clock should exceed 1.8V, and its low amplitude should be below 0.4V to drive the internal logic. The recommended external SYNC frequency is ±15% of the set f_{SW} (between 2MHz and 4MHz).

When there is a SYNC clock, the MPQ2288 operates in FCCM with a fixed frequency, regardless of I_{OUT}. A pulse longer than 200ns is recommended. Connect SYNCIN to AGND using a resistor if it is not used.

SYNCOUT

The MPQ2288 can output the internal clock with a 0° or 180° phase shift. With this function, two devices can operate at the same frequency, but 180° out of phase to reduce the total input current ripple. This allows a lower-value input bypass capacitor to be used.

Soft Start (SS)

Soft start (SS) is implemented to prevent V_{OUT} from overshooting during start-up. When the MPQ2288 starts up, the internal circuitry generates a soft-start voltage (V_{SS}) that ramps up from 0V. The soft-start time (t_{SS}) lasts until V_{SS} on the soft-start capacitor (C_{SS}) exceeds the reference voltage (V_{REF}). At this point, the error amplifier (EA) uses V_{REF} as the reference. There are four available SS slew rates, which can be configured via the OTP.

Soft Shutdown

There are four available shutdown slew rates to set the soft-shutdown time, which can be enabled via the OTP. Soft shutdown is implemented to discharge V_{OUT}. When the MPQ2288 starts to turn off, V_{REF} ramps down and V_{OUT} follows, causing the charge to transfer from the output to the input. The soft-shutdown slew rates can be configured via the OTP.

Minimum On Time (t_{ON_MIN}) and Minimum Off Time (t_{OFF_MIN})

When the device triggers the minimum on time (t_{ON_MIN}) (26ns), the MPQ2288's control loop automatically skips some pulses. The part does not decrease the frequency once the minimum off time (t_{OFF_MIN}) (100ns) is triggered. This means that for applications with a low V_{IN} and a high V_{OUT}, V_{OUT} drops once the device reaches t_{OFF_MIN}.

Output Discharge

An optional 120Ω discharge MOSFET is available, which can be configured via the OTP. When enabled, the discharge MOSFET turns on after the part is disabled. This MOSFET continues to operate as long as V_{IN} exceeds 2.4V.

Pre-Biased Start-Up

If V_{OUT} exceeds 0V at start-up, both the HS-FET and LS-FET remain off until V_{SS} reaches V_{OUT}.

Power Good (PG) Indicator

The power good (PG) indicator is an open-drain output that indicates whether V_{OUT} is within the PG thresholds. PG can be connected to VCC through an external resistor (e.g. 100kΩ). When using the VCC pin as pull-up voltage source, PG will be at a low level when the part is disabled with EN=0V. When using the VCC pin as a pull-up voltage source, PG is at a low level when the part is disabled and EN = 0V. When using pull-up voltage sources other than VCC, an external circuit should be added to ensure that PG is at a low level when the part is disabled and EN = 0V (see Figure 3).

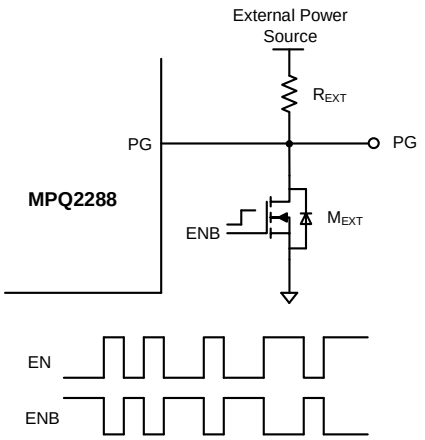


Figure 3: Recommended External Circuit for PG

The pin asserts (pulls low) if V_{OUT} is outside of the PG thresholds, the output is off, or if soft start/soft shutdown occurs. PG can also be configured to indicate thermal warning or PMBus interface communication failures via the OTP.

Table 1 shows the PG state based on different device input values if V_{IN} is present.

Table 1: PG State with V_{IN} Present

Circuit Configuration	EN	VCC	V_{OUT}	PG
PG Pulled Up to VCC	<0.65V	Off	-	Low
	0.65V ≤ V_{EN} < 1.2V	On	-	Low
	≥1.2V	On	Out of range	Low
	≥1.2V	On	In range	High
PG Pulled Up to an External Source	<0.65V	Off	-	High
	0.65V ≤ V_{EN} < 1.2V	On	-	Low
	≥1.2V	On	Out of range	Low
	≥1.2V	On	In range	High

Over-Current Protection (OCP)

The MPQ2288 implements cycle-by-cycle over-current protection (OCP) to limit I_{OUT}. The peak and valley current limits ensure protection regardless of the duty cycle. The OTP can set whether OCP causes a hiccup.

If I_L reaches the high-side (HS) peak I_{LIMIT} (I_{LIMIT_HS}) while the HS-FET is on, the HS-FET is forced off immediately to prevent the current from rising further. If the clock is received before I_L reaches I_{LIMIT_HS}, the HS-FET also turns off due to the clock.

When the LS-FET is on, the next clock rising edge is held until I_L drops below the low-side (LS) valley I_{LIMIT} (I_{LIMIT_LS}). When the HS-FET turns on again, I_L can drop to a sufficiently low value. This I_{LIMIT} scheme prevents current runaway if an overload or short-circuit occurs. When OCP hiccup mode is enabled via the OTP, the output shuts off for the hiccup time after the valley current limit is triggered for a certain time (can be configured via the OTP). Then the device restarts with a full SS.

Short-Circuit Protection (SCP) and Under-Voltage Protection (UVP)

If V_{OUT} is below 75% of the configured V_{OUT}, short-circuit protection (SCP) and output under-voltage protection (UVP) are triggered. The output shuts off for the hiccup time, and restarts with a full t_{SS}. Output UVP can be enabled or disabled via the OTP. If enabled, the output discharge function operates during hiccup mode.

Output Over-Voltage Protection (OVP)

If V_{OUT} exceeds the output over-voltage protection (OVP) threshold, that output shuts off during hiccup mode, and then the normal soft-start process begins again. Output OVP can be enabled or disabled via the OTP. If enabled, the output discharge function operates during hiccup mode.

Input Over-Voltage Protection (OVP)

If V_{IN} exceeds 6.7V, input OVP is triggered. The MPQ2288 starts operating once V_{IN} drops below the input OVP threshold (OVP rising threshold - OVP hysteresis).

Thermal Warning (TW)

If the die temperature exceeds the thermal warning (TW) threshold (typically 140°C), the thermal warning register asserts. PG can be configured to indicate whether a thermal warning has occurred via the PG_MAPPING register.

Thermal Shutdown (TSD)

If the die temperature exceeds the thermal shutdown (TSD) threshold (typically 170C°), the MPQ2288 disables switching and the PG pin asserts.

Multi-Page One-Time Programmable (OTP) Memory

The MPQ2288 features two user pages of OTP memory to store settings permanently.

For long-term reliability, a differential OTP cell is used instead of a single-ended cell. Data is stored on two floating gate avalanche injection metal oxide semiconductors (FAMOS), and output comparators are used for differential reading.

Only the MPQ2288-0000 version has an OTP memory that can be written twice; all other versions/codes have an OTP memory that can only be written once, or not at all. The OTP

memory can be written via the dedicated STORE_USER_ALL (15h) command.

Cyclic Redundancy Check (CRC)

The OTP memory is protected by a cyclic redundancy check (CRC). If the calculated CRC value does not match the recorded value during start-up, the device does not start up .

Remote Output Voltage (V_{OUT}) Sensing

Remote V_{OUT} sensing is implemented to compensate for the voltage drop caused by the large I_{OUT} and the resistance in the transmission line in the copper between the MPQ2288 and the load. Figure 4 shows the remote V_{OUT} sensing circuit. Connect the VOUT+ and VOUT- pins close to the load using a Kelvin connection to accurately sense V_{OUT}. Ensure that there are enough capacitors to support the voltage at the load terminal.

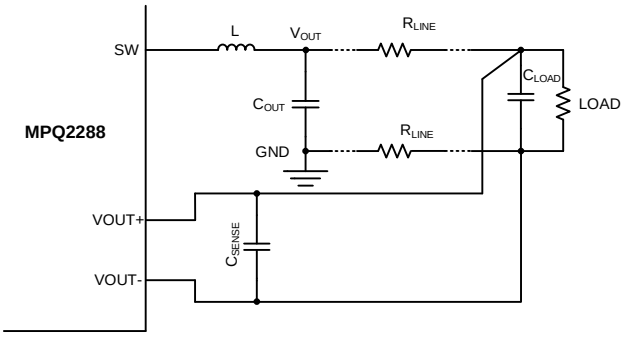


Figure 4: Remote V_{OUT} Sensing Circuit

DIGITAL INTERFACE

Serial Digital Interface Description

The digital interface is an open-standard, power-management protocol that defines a means of communication with power conversion and other devices. It is a two-wire, bidirectional serial interface, consisting of a serial data line (SDA) and a serial clock line (SCL). The lines are externally pulled to a bus voltage when they are idle. Connecting to the line, a master device generates the SCL signal and device address, and arranges the communication sequence.

The MPQ2288 works as a slave-only device, which supports fast-mode plus (1Mbps) bidirectional data transfer, adding flexibility to the power supply solution. V_{OUT}, the transition slew rate, and other converter parameters can be instantaneously controlled via the digital interface.

Data Validity

One clock pulse is generated for each data bit transferred. The data on the SDA line must be stable during the clock's high period. The SDA line's high or low state can only change when the SCL line's clock signal is low (see Figure 5).

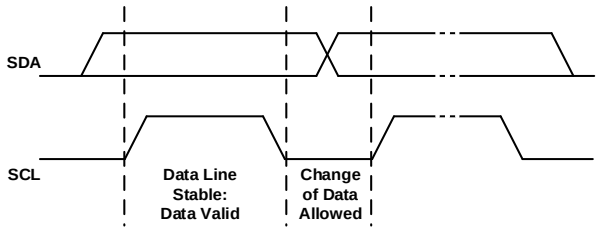


Figure 5: Bit Transfer on the Digital Interface

Start and Stop Commands

The start and stop commands are signaled by the master device, which signifies the beginning and the end of the digital interface transfer. A start (S) command is defined as the SDA signal transitioning from high to low while SCL is high. A stop (P) command is defined as the SDA signal transitioning from low to high while SCL is high (see Figure 6).

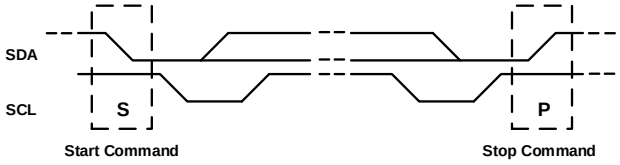


Figure 6: Start and Stop Command

Start and stop commands are always generated by the master device. The bus is considered busy after the start command. The bus is considered free again after a certain time after the stop command. The bus stays busy if a repeated start (Sr) command is generated instead of a stop command. The start and repeated start commands are functionally identical.

Data Transfer

Every byte put on the SDA line must be 8 bits long. Each byte must be followed by an acknowledge (ACK) bit. The acknowledge-related clock pulse is generated by the master device. The transmitter releases the SDA line (high) during the acknowledge clock pulse. The receiver must pull down the SDA line during the acknowledge clock pulse, so that it remains stable low during the high period of the clock pulse.

Figure 7 shows the data transfer format. After the start command, a slave address is sent. This address is 7 bits long, followed by an 8th data direction bit (R/W). A 0 indicates a transmission (write), and a 1 indicates a request for data (read). Data transfer is always terminated by a stop command, which is generated by the master device. However, if a master device still wishes to communicate on the bus, it can generate a repeated start command and address another slave device without first generating a stop command.

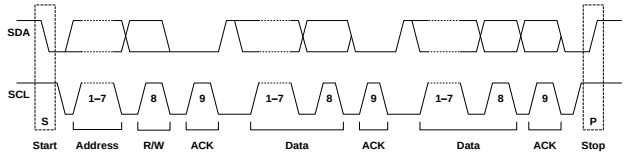


Figure 7: Complete Data Transfer

Packet Error Checking (PEC)

The PEC mechanism is employed to improve communication reliability and robustness. Whenever applicable, PEC is implemented by appending a packet error code after the data of each message transfer.

The packet error code is a CRC-8 error-checking byte, calculated on all the message bytes, including addresses and read/write (R/W) bits.

The code is appended to the message by the device that supplied the last data byte.

If an incorrect code is received, a communications fault is triggered. The power good (PG) flag asserts until the fault register is cleared.

Digital Interface Communication Failure

A data transmission fault occurs when the data is not properly transferred between the devices. There are several possible data transmission faults:

- The host sends too little data
- The host reads too little data
- The host sends too many bytes
- The host reads too many bytes
- Improperly set read bit in the address byte
- Unsupported command code

The communication failure is recorded in the STATUS_CML register.

Write/Read Sequence

All digital interface commands are supported by the MPQ2288. There are five kinds of commands that can be implemented with or without PEC:

1) Send command only
2) Write byte
3) Write word
4) Read byte
5) Read word

If the master device writes a command to a read-only register, the MPQ2288 performs the same action as it would if the host sent too many bytes. If the master device sends a read command from a write-only register, the MPQ2288 performs the same action as it would if the host read too many bytes.

Figure 8 shows the write/read sequence without PEC. Figure 9 on page 37 shows the write/read sequence with PEC.

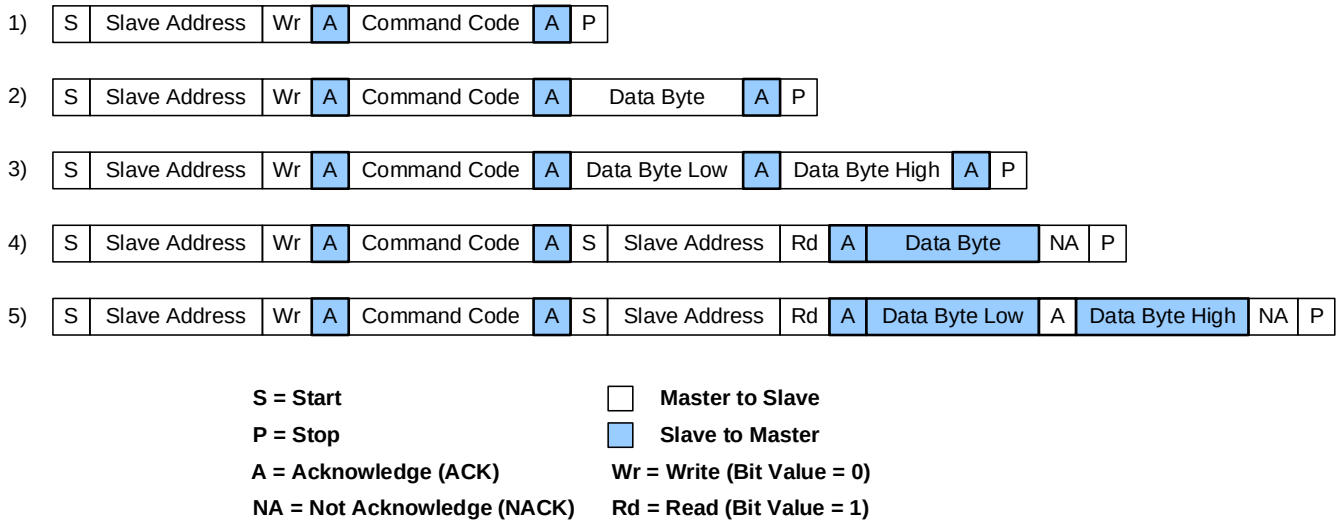


Figure 8: Digital Interface Write/Read Sequence without PEC

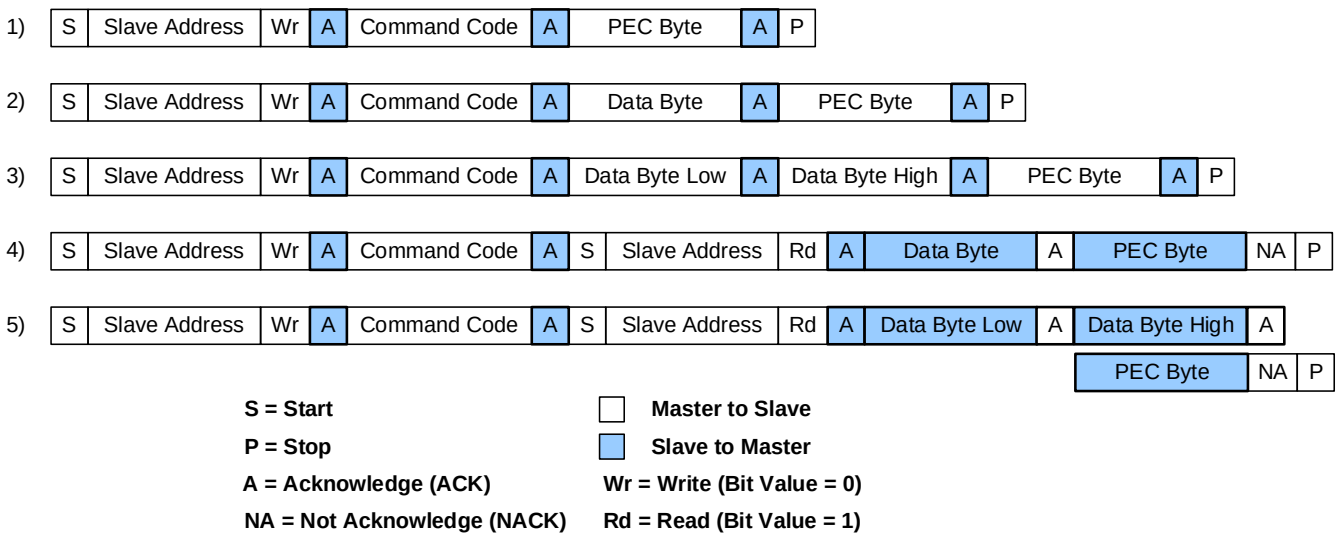


Figure 9: Digital Interface Write/Read Sequence with PEC

STATE MACHINE DESCRIPTION

The state machine describes the different states of operation. There are six states in the device: POWER OFF, RESTORE_OTP, START-UP, NORMAL, STORE_USER, and RESTORE_USER (see Figure 10).

Each state is described in greater detail below.

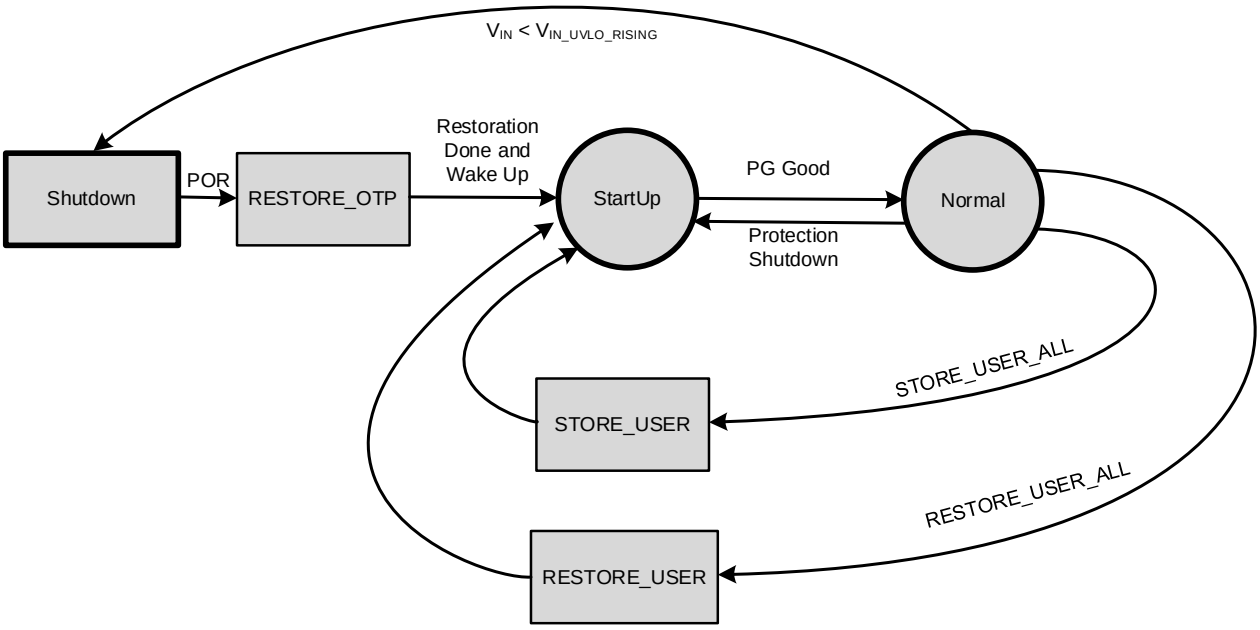


Figure 10: System State Machine

Shutdown State (POWER_OFF)

The MPQ2288 is in the shutdown state as long as the power-on reset (POR) is not released.

Restore the One-Time Programmable (OTP) Memory State (RESTORE_OTP)

Once the input voltage (V_{IN}) exceeds its UVLO rising threshold ($V_{IN\_UVLO\_RISING}$), POR is released. The MPQ2288 restores the registers from the embedded one-time programmable (OTP) memory content data. Once restoration is complete, the MPQ2288 automatically enters the start-up state.

Start-Up State (START-UP)

Once OTP restoration is complete and the wake-up signal is enabled, the device enters the start-up state. All other supplies are enabled and the output starts to ramp up in the start-up state.

Normal State (NORMAL)

The MPQ2288 enters the normal state as soon as the output regulator voltage is power good (PG). The normal state is the MPQ2288's standard operating state, during which the output regulator is running.

Store User State (STORE_USER)

The store user state writes the present data from the registers to the internal OTP content. Then the MPQ2288 transitions to the start-up state and restarts. Only writing to the STORE_USER_ALL register from the normal state can force the device to enter the store user state. See the STORE_USER_ALL (15h) section on page 40 for more details.

Restore User State (RESTORE_USER)

The restore user state copies all of the OTP values to the matching locations in the registers. The values in the registers are overwritten by the value retrieved from the OTP. Any items in the OTP that do not have matching locations in the operating memory are ignored. Then the MPQ2288 transitions to the start-up state and restarts. Only writing to the RESTORE_USER_ALL register from the normal state can force the device to enter the restore user state. See the RESTORE_USER_ALL (16h) section on 40 for more details.

REGISTER MAP

Command Code	Command Name	Type	Bytes	OTP	Page 0
01h	OPERATION	R/W	1	Yes	✓
03h	CLEAR_FAULTS	W	0	No	✓
10h	WRITE_PROTECT	R/W	1	No	✓
15h	STORE_USER_ALL	W	0	No	✓
16h	RESTORE_USER_ALL	W	0	No	✓
19h	CAPABILITY	R	1	No	✓
20h	VOUT_MODE	R	1	No	✓
21h	VOUT_COMMAND	R/W	1	Yes	✓
24h	VOUT_MAX	R/W	1	Yes	✓
29h (13)	VOUT_SCALE	R/W	1	Yes	✓
2Bh	VOUT_MIN	R/W	1	Yes	✓
60h	TON_DELAY	R/W	1	Yes	✓
64h	TOFF_DELAY	R/W	1	Yes	✓
78h	STATUS_BYTE	R/W	1	No	✓
79h	STATUS_WORD	R/W	2	No	✓
7Ah	STATUS_VOUT	R/W	1	No	✓
7Bh	STATUS_IOUT	R/W	1	No	✓
7Ch	STATUS_INPUT	R/W	1	No	✓
7Dh	STATUS_TEMPERATURE	R/W	1	No	✓
7Eh	STATUS_CML	R/W	1	No	✓
9Bh	MFR_REVISION	R	1	No	✓
C4h	SECURE_LOCKOUT	R/W	1	No	✓
C5h	HICCUP_TIMER	R/W	1	Yes	✓
C6h	VOUT_STARTUP_SLEW	R/W	1	Yes	✓
C7h	VOUT_SHUTDOWN_SLEW	R/W	1	Yes	✓
C8h	VOUT_SLEW	R/W	1	Yes	✓
C9h	OUTPUT_DISCHARGE	R/W	1	Yes	✓
CAh	FREQUENCY_DITHER	R/W	1	Yes	✓
CBh	FREQUENCY_SET	R/W	1	Yes	✓
CCh	COMPENSATION_CONFIG	R/W	2	Yes	✓
CEh	PROTECTION_CONFIG	R/W	1	Yes	✓
CDh	PG_MAPPING	R/W	1	Yes	✓
CFh	PG_DELAY	R/W	1	Yes	✓
D0h	PG_CONFIG	R/W	1	Yes	✓
D1h	LIGHT_LOAD	R/W	1	Yes	✓
D2h	ILIM_SCALE	R/W	1	Yes	✓
D3h	ADDRESS	R/W	1	Yes	✓
D4h	CONFIGURATION_CODE	R	1	Yes	✓
D5h	MEMORY_CRC	R	2	Yes	✓
D6h	LATEST_PEC	R	1	No	✓
D8h	MFR_OTP_MEM_STATUS	R	1	No	✓
DBh	ADVANCED_CONFIG	W	1	No	✓
DCh	SUMMING_BLOCK_CONFIG	R/W	1	Yes	✓
DDh	MIN_ON_CONFIG	R/W	1	Yes	✓

Note:

13) This register value cannot be modified while the device is operating. Disable the output before modifying this register.

REGISTER MAP (PAGE 0)

OPERATION (01h)

Format: Unsigned binary

The OPERATION command on Page 0 configures the converter's output on/off state, in conjunction with the input from the EN pin.

Bits	Access	Bit Name	Default	Description
7	R/W	OPERATION	1'b1	1'b1: Output on (if enabled high) 1'b0: Output off
6:0	R	RESERVED	-	Unused. Writes are ignored and always read as 0.

CLEAR_FAULTS (03h)

The CLEAR_FAULTS command on Page 0 clears any fault bit in all status registers: STATUS_BYTE (78h), STATUS_WORD (79h), STATUS_VOUT (7Ah), STATUS_INPUT (7Ch), STATUS_TEMPERATURE (7Dh), and STATUS_CML (7Eh).

This command is write-only. There is no data byte for this command.

WRITE_PROTECT (10h)

Format: Unsigned binary

The WRITE_PROTECT command on Page 0 controls writing to the converter. The intent of this command is to provide protection against accident changes. It is not intended to provide protection against deliberate changes to the converter's configuration or operation. All supported commands may have their parameters read, regardless of the WRITE_PROTECT settings.

Bits	Access	Bit Name	Default	Description
7:0	R/W	WRITE_PROTECT	8'b00000000	8'b10000000: Disables all writes except to the WRITE_PROTECT command 8'b01000000: Disables all writes except to the WRITE_PROTECT, OPERATION, and PAGE commands 8'b00100000: Disables all writes except to the WRITE_PROTECT, OPERATION, PAGE, and VOUT_COMMAND commands 8'b00000000: Enables writes to all commands Others: Invalid commands

STORE_USER_ALL (15h)

The STORE_USER_ALL command on Page 0 instructs the MPQ2288 to copy the contents of the operating memory to the matching locations in the OTP, except for the internal trim registers. This process begins when the MPQ2288 receives a STORE_USER_ALL command from the digital interface.

This command is write-only. There is no data byte for this command.

RESTORE_USER_ALL (16h)

The RESTORE_USER_ALL command on Page 0 instructs the MPQ2288 to copy the contents from the OTP and overwrite the matching locations in the operating memory, except for the trim registers. Any items in the OTP that do not have matching locations in the operating memory are ignored.

The RESTORE_USER_ALL command can be used while the MPQ2288 is operating. However, the MPQ2288 may be unresponsive during this operation with unpredictable, undesirable, or even catastrophic results.

This command is write-only. There is no data byte for this command.

CAPABILITY (19h)

Format: Unsigned binary

The CAPABILITY command on Page 0 provides 1 byte to return key digital interface features that the MPQ2288 can support.

Bits	Access	Bit Name	Default	Description
7	R	PACKET_ERR_CHECKING	1'b1	1'b1: Packet error checking (PEC) is supported Others: Invalid commands
6:5	R	MAX_BUS_SPEED	2'b10	2'b10: The maximum supported bus speed is 1MHz Others: Invalid commands
4	R	SMBALERT#	1'b0	1'b0: The device does not have an SMBALERT# pin and does not support the SMBus Alert Response protocol Others: Invalid commands
3	R	NUMERIC_FORMAT	1'b0	1'b0: Numeric data is in Linear11, ULinear16, Slinear16, or direct format Others: Invalid commands
2	R	AVSBUS_SUPPORT	1'b0	1'b0: AVSBus is not supported Others: Invalid commands
1:0	R	RESERVED	-	Reserved.

VOUT_MODE (20h)

Format: Unsigned binary

The VOUT_MODE command on Page 0 commands and reads the V_{OUT} mode. The 3MSB determine the data format (only direct format is supported by the MPQ2288).

Bits	Access	Bit Name	Default	Description
7:0	R	VOUT_MODE	8'b01000000	8'b01000000: Direct mode. The coefficients are m = 160, R = 0, and b = -33 Others: Invalid commands

VOUT_COMMAND (21h)

Format: Unsigned binary

The VOUT_COMMAND command on Page 0 sets V_{OUT}.

Bits	Access	Bit Name	Default	Description
7:0	R/W	VOUT_CMD	8'b01111111	V_{OUT} can be calculated with the following equation: V_{OUT} = (VOUT_CMD x 6.25mV + 206.25mV) x VOUT_SL If VOUT_SL = 1, then V_{OUT} can be set between 0.5V and 1.8V. If VOUT_SL = 2, then V_{OUT} can be set between 0.5V and 3.6V.

VOUT_MAX (24h)

Format: Unsigned binary

The VOUT_MAX command on Page 0 sets the upper V_{OUT} limit that the converter can command, regardless of any other commands or combinations. The intent of this command is to provide a safeguard against a user accidentally setting V_{OUT} to a possibly destructive level, rather than to be the primary V_{OUT} over-voltage protection (OVP).

Bits	Access	Bit Name	Default	Description
7:0	R/W	VOUT_MAX	8'b11111111	Sets the maximum V_{OUT}, which can be calculated with the following equation: V_{OUT_MAX} = (VOUT_MAX x 6.25mV + 206.25mV) x VOUT_SL If VOUT_SL = 1, then V_{OUT} can be set between 0.5V and 1.8V. If VOUT_SL = 2, then V_{OUT} can be set between 0.5V and 3.6V. Attempting to write a higher value to VOUT_COMMAND causes VOUT_COMMAND to be set to V_{OUT_MAX} and asserts a VOUT_MAX_MIN warning.

VOUT_SCALE_LOOP (29h)

Format: Unsigned binary

The VOUT_SCALE_LOOP command on Page 0 sets the V_{OUT} scale.

Bits	Access	Bit Name	Default	Description
7:1	R/W	RESERVED	N/A	Reserved.
0	R/W	VOUT_SC_L	1'b0	Sets the V_{OUT} scale. Direct mode. The coefficients are m = 1, R = 0, and b = -1. 1'b0: VOUT_SL = 1 1'b1: VOUT_SL = 2

VOUT_MIN (2Bh)

Format: Unsigned binary

The VOUT_MIN command on Page 0 sets the lower V_{OUT} limit that the converter can command, regardless of any other commands or combinations. The intent of this command is to provide a safeguard against a user accidentally setting V_{OUT} to a possibly destructive level, rather than to be the primary V_{OUT} under-voltage protection (UVP).

Bits	Access	Bit Name	Default	Description
7:0	R/W	VOUT_MIN	8'b00000000	Sets the minimum V_{OUT}, which can be calculated with the following equation: V_{OUT_MIN} = (VOUT_MIN x 6.25mV + 206.25mV) x VOUT_SL If VOUT_SL = 1, then V_{OUT} can be set between 0.5V and 1.8V. If VOUT_SL = 2, then V_{OUT} can be set between 0.5V and 3.6V. Attempting to write a lower value to VOUT_COMMAND causes VOUT_COMMAND to be set to V_{OUT_MIN} and asserts a VOUT_MAX_MIN warning.

TON_DELAY (60h)

Format: Unsigned binary

The TON_DELAY command on Page 0 sets the start-up delay time.

Bits	Access	Bit Name	Default	Description
7:5	R/W	RESERVED	-	Reserved.

4:0	R/W	TON_DELAY	5'b00000	Sets the start-up delay time, calculated with the following equation: Start-Up Delay = TON_DELAY x 0.25ms The delay can be set between 0ms and 7.75ms.

TOFF_DELAY (64h)

Format: Unsigned binary

The TOFF_DELAY command on Page 0 sets the shutdown delay time.

Bits	Access	Bit Name	Default	Description
7:5	R/W	RESERVED	-	Reserved.
4:0	R/W	TOFF_DELAY	5'b00000	Sets the shutdown delay time, calculated with the following equation: Shutdown Delay = TOFF_DELAY x 0.25ms The delay can be set between 0ms and 7.75ms.

STATUS_BYTE (78h)

Format: Unsigned binary

The STATUS_BYTE command on Page 0 returns the value of a number of flags indicating the state of the MPQ2288. Send a CLEAR_FAULTS (03h) command to clear the fault flag bits after the fault is removed. See the CLEAR_FAULTS (03h) section on page 40 for more details.

Bits	Access	Bit Name	Default	Description
7	R/W	BUSY	1'b0	1'b0: No busy fault has occurred 1'b1: A fault was declared because the device was busy and unable to respond
6	R/W	OFF	1'b0	1'b0: The device is on 1'b1: The device is off
5	R/W	VOUT_OV_FAULT	1'b0	1'b0: No output over-voltage (OV) fault has occurred 1'b1: An output OV fault has occurred
4	R/W	IOUT_OC_HICCUP_FAULT	1'b0	1'b0: No output over-current (OC) hiccup fault has occurred 1'b1: An output OC hiccup fault has occurred
3	R/W	RESERVED	-	Reserved.
2	R/W	TEMPERATURE	1'b0	1'b0: No temperature fault or warning has occurred 1'b1: A temperature fault or warning has occurred
1	R/W	CML	1'b0	1'b0: No communications, memory, or logic fault has occurred 1'b1: A communications, memory, or logic fault has occurred
0	R/W	FAULT_OTHER	1'b0	1'b0: No other fault has occurred 1'b1: A fault not covered by bits[7:1] of this command has occurred

STATUS_WORD (79h)

Format: Unsigned binary

The STATUS_WORD command on Page 0 returns 2 bytes of information with a summary of the device's fault/warning conditions. The higher byte provides more detailed information of the fault conditions. The lower byte is shared with register STATUS_BYTE (78h). Send a CLEAR_FAULTS (03h) command to clear the fault flag bits after the fault is removed. See the CLEAR_FAULTS (03h) section on page 40 for more details.

Bits	Access	Bit Name	Default	Description
15	R/W	VOUT_FAULT	1'b0	1'b0: No output voltage (V_{OUT}) fault has occurred 1'b1: A V_{OUT} fault has occurred
14	R/W	IOUT_FAULT	1'b0	1'b0: No output current (I_{OUT}) fault has occurred 1'b1: An I_{OUT} fault has occurred
13	R/W	VIN_FAULT	1'b0	1'b0: No input voltage (V_{IN}) fault has occurred 1'b1: A V_{IN} fault has occurred
12	R/W	MANUFAC_FAULT	1'b0	1'b0: No manufacturer-specific fault has occurred 1'b1: A manufacturer-specific fault has occurred
11	R/W	PGOOD	1'b0	1'b0: PG is high 1'b1: PG is low
10:8	R/W	RESERVED	-	Reserved.
Low byte (7:0)	R/W	STATUS_BYTE	8'b00000000	The same as STATUS_BYTE (78h).

STATUS_VOUT (7Ah)

Format: Unsigned binary

The STATUS_VOUT command on Page 0 returns detailed fault information. Clear the fault flag bit by writing 1 to the relevant fault bit after that fault has been removed.

Bits	Access	Bit Name	Default	Description
7	R/W	VOUT_OV_FAULT	1'b0	1'b0: No V_{OUT} over-voltage (OV) fault has occurred 1'b1: A V_{OUT} OV fault has occurred
6:5	R/W	RESERVED	-	Reserved.
4	R/W	VOUT_UV_FAULT	1'b0	1'b0: No V_{OUT} under-voltage (UV) fault has occurred 1'b1: A V_{OUT} UV fault has occurred
3	R/W	VOUT_MAX_MIN_WARN	1'b0	1'b0: No attempt to set V_{OUT} beyond V_{OUT_MIN} or V_{OUT_MAX} has occurred 1'b1: An attempt to set V_{OUT} beyond V_{OUT_MIN} or V_{OUT_MAX} has occurred
2:0	R/W	RESERVED	-	Reserved.

STATUS_IOUT (7Bh)

Format: Unsigned binary

The STATUS_IOUT command on Page 0 returns detailed fault information. Clear the fault flag bit by writing 1 to the relevant fault bit after that fault has been removed.

Bits	Access	Bit Name	Default	Description
7	R/W	IOUT_OC_HICCUP_FAULT	1'b0	1'b0: No I_{OUT} over-current (OC) hiccup fault has occurred 1'b1: An I_{OUT} OC hiccup fault has occurred
6:0	R/W	RESERVED	-	Reserved.

STATUS_INPUT (7Ch)

Format: Unsigned binary

The STATUS_INPUT command on Page 0 returns detailed fault information. Clear the fault flag bit by writing 1 to the relevant fault bit after that fault has been removed.

Bits	Access	Bit Name	Default	Description
7	R/W	VIN_OV_FAULT	1'b0	1'b0: No V_{IN} over-voltage (OV) fault has occurred 1'b1: A V_{IN} OV fault has occurred
6:0	R/W	RESERVED	-	Reserved.

STATUS_TEMPERATURE (7Dh)

Format: Unsigned binary

The STATUS_ TEMPERATURE command on Page 0 returns detailed fault information. Clear the fault flag bit by writing 1 to the relevant fault bit after that fault has been removed.

Bits	Access	Bit Name	Default	Description
7	R/W	TEMP_OT_FAULT	1'b0	1'b0: No over-temperature (OT) fault has occurred 1'b1: An OT fault has occurred
6	R/W	TEMP_OT_ WARNING	1'b0	1'b0: No OT warning has occurred 1'b1: An OT warning has occurred
5:0	R/W	RESERVED	-	Reserved.

STATUS_CML (7Eh)

Format: Unsigned binary

The STATUS_CML command on Page 0 returns detailed fault information. Clear the fault flag bit by writing 1 to the relevant fault bit after that fault has been removed.

Bits	Access	Bit Name	Default	Description
7	R/W	INVALID_CMD	1'b0	1'b0: No invalid or unsupported command has been received 1'b1: An invalid or unsupported command has been received
6	R/W	INVALID_DATA	1'b0	1'b0: No invalid or unsupported data has been received 1'b1: Invalid or unsupported data has been received
5	R/W	PEC_ERROR	1'b0	1'b0: No PEC failure has occurred 1'b1: A PEC failure has occurred
4	R/W	MEMORY_FAULT	1'b0	1'b0: No CRC failure has occurred 1'b1: A CRC failure has occurred
3:0	R/W	RESERVED	-	Reserved.

SECURE_LOCKOUT (C4h)

Format: Unsigned binary

The SECURE_LOCKOUT command on Page 0 locks out access to most registers.

Bits	Access	Bit Name	Default	Description
7:0	R/W	SECURE_LOCKOUT	8'b00000000	Write 01011010 to lockout write access to most registers. Registers listed as "No" under the "Lockout?" column in the Register Map section starting on page 39 can still be written. These bits can only be cleared by setting all enables to low. Other commands are invalid.

HICCUP_TIMER (C5h)

Format: Unsigned binary

The HICCUP_TIMER command on Page 0 sets the hiccup timer.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1:0	R/W	HICCUP_TIMER	2'b01	2'b00: 2ms 2'b01: 4ms 2'b10: 6ms 2'b11: 8ms

VOUT_STARTUP_SLEW (C6h)

Format: Unsigned binary

The VOUT_STARTUP_SLEW command on Page 0 sets the start-up slew rate.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1:0	R/W	VOUT_STARTUP_ SLEW	2'b00	2'b00: VOUT_SL x 1.25mV/µs 2'b01: VOUT_SL x 2.5mV/µs 2'b10: VOUT_SL x 5mV/µs 2'b11: VOUT_SL x 10mV/µs

VOUT_ SHUTDOWN _SLEW (C7h)

Format: Unsigned binary

The VOUT_SHUTDOWN_SLEW command on Page 0 sets the shutdown slew rate.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	N/A	Reserved.
1:0	R/W	VOUT_SHUTDOWN_ SLEW	2'b00	2'b00: VOUT_SL x 1.25mv/µs 2'b01: VOUT_SL x 2.5mv/µs 2'b10: VOUT_SL x 5mv/µs 2'b11: VOUT_SL x 10mv/µs

VOUT_SLEW (C8h)

Format: Unsigned binary

The VOUT_SLEW command on Page 0 sets the V_{OUT} slew rate.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1:0	R/W	VOUT_SLEW	2'b00	2'b00: VOUT_SL x 2.5mv/µs 2'b01: VOUT_SL x 5mv/µs 2'b10: VOUT_SL x 10mv/µs 2'b11: VOUT_SL x 20mv/µs

OUTPUT_DISCHARGE (C9h)

Format: Unsigned binary

The OUTPUT_DISCHARGE command on Page 0 configures the discharge mode during shutdown.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1	R/W	SS_EN	1'b0	1'b0: Soft shutdown disabled 1'b1: Soft shutdown enabled

0	R/W	DISCHARGE_EN	1’b0	1’b0: 120Ω output discharge disabled 1’b1: 120Ω output discharge enabled

FREQUENCY_DITHER (CAh)

Format: Unsigned binary

The FREQUENCY_DITHER command on Page 0 enables frequency spread spectrum (FSS).

Bits	Access	Bit Name	Default	Description
7:1	R/W	RESERVED	-	Reserved.
0	R/W	FREQUENCY_ DITHER	1’b1	Enables FSS. 1’b0: Disabled 1’b1: Enabled

FREQUENCY_SET (CBh)

Format: Unsigned binary

The FREQUENCY_SET command on Page 0 sets the synchronous (SYNC) output phase and the switching frequency (f_{SW}).

Bits	Access	Bit Name	Default	Description
7:3	R/W	RESERVED	-	Reserved.
2	R/W	SYNCO_PHASE	1’b1	Sets the SYNC output phase. 1’b0: 180° 1’b1: 0°
1:0	R/W	FREQUENCY_SET	2’b00	Sets f_{SW}. 2’b00: 2MHz 2’b01: 2.2MHz 2’b10: 3MHz 2’b11: 4MHz

COMPENSATION_CONFIG (CCh)

Format: Unsigned binary

The COMPENSATION_CONFIG command on Page 0 configures the compensation network parameters.

Bits	Access	Bit Name	Default	Description
15:10	R/W	RESERVED	-	Reserved.
9:7	R/W	CCOMP	3’b000	Sets C_{COMP}. 3’b000: 30pF 3’b001: 10pF 3’b010: 20pF 3’b011: 0pF 3’b100: 50pF 3’b110: 40pF Others: Invalid commands
6:4	R/W	CPOLE	3’b000	Sets C_{POLE}, calculated with the following equation: C_{POLE} = (COMPENSATION_CONFIG x 0.1pF + 20pF)

3:0	R/W	RCOMP	4’b0000	Sets R_{COMP}. 4’b0000: 20Ω 4’b0001: 25kΩ 4’b0010: 50kΩ 4’b0011: 75kΩ 4’b0100: 100kΩ 4’b0101: 125kΩ 4’b0110: 150kΩ 4’b0111: 175kΩ 4’b1001: 225kΩ 4’b1010: 250kΩ 4’b1011: 275kΩ 4’b1100: 300kΩ 4’b1101: 325kΩ 4’b1110: 350kΩ 4’b1111: 400kΩ Others: Invalid commands

PROTECTION_CONFIG (CEh)

Format: Unsigned binary

The PROTECTION_CONFIG command on Page 0 enables certain functions.

Bits	Access	Bit Name	Default	Description
7:5	R/W	RESERVED	-	Reserved.
4	R/W	VIN_ OVP_EN	1’b1	1’b0: Disable V_{IN} over-voltage protection (OVP) 1’b1: Enable V_{IN} OVP
3:2	R/W	OCP_CONFIG	2’b11	Configures whether over-current protection (OCP) causes a hiccup. 2’b00: OCP does not directly cause a hiccup 2’b01: 16µs internal OCP signal of an OC condition causes a hiccup 2’b10: 32us internal OCP signal of an OC condition causes a hiccup 2’b11: 64us internal OCP signal of an OC condition causes a hiccup
1	R/W	VOUT_OVP_EN	1’b0	1’b0: Disable V_{OUT} OVP 1’b1: Enable V_{OUT} OVP
0	R/W	VOUT_UVP_EN	1’b0	1’b0: Disable V_{OUT} under-voltage protection (UVP) 1’b1: Enable V_{OUT} UVP

PG_MAPPING (CDh)

Format: Unsigned binary

The PG_MAPPING command on Page 0 configures whether PG pulls low for certain digital interface and thermal warning errors.

Bits	Access	Bit Name	Default	Description
7:3	R/W	RESERVED	-	Reserved.
2	R/W	PM_CML_PG_ MAPPING	1’b0	Maps PG for digital interface communication failures. 1’b0: A digital interface communication failure causes PG to be pulled low and register assertion 1’b1: A digital interface communication failure causes register assertion only

1	R/W	PM_CRC_ PGMAPPING	1’b0	Maps PG for a digital interface CRC failure. 1’b0: A digital interface CRC failure causes PG to be pulled low and register assertion 1’b1: A digital interface CRC failure cause register assertion only
0	R/W	THERMAL_WARN_ PGMAPPING	1’b0	Maps PG for a thermal warning. 1’b0: A thermal warning causes PG to be pulled low and register assertion 1’b1: A thermal warning causes register assertion only

PG_DELAY (CFh)

Format: Unsigned binary

The PG _DELAY command on Page 0 sets the de-assertion delay for PG.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1:0	R/W	PG_DELAY	2’b00	Sets the PG de-assertion delay. 2’b00: Immediate 2’b01: 2ms 2’b10: 5ms 2’b11: 10ms

PG_CONFIG (D0h)

Format: Unsigned binary

The PG_CONFIG command on Page 0 sets the PG threshold.

Bits	Access	Bit Name	Default	Description
7:1	R/W	RESERVED	-	Reserved.
0	R/W	PG_THRESHOLD	1’b1	Sets the PG threshold. 1’b0: ±4% of the set value 1’b1: ±6% of the set value

LIGHT_LOAD (D1h)

Format: Unsigned binary

The LIGHT_LOAD command on Page 0 sets the operation mode under light-load conditions.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1	R/W	USM	1’b0	Sets the minimum frequency for ultrasonic mode (USM). 1’b0: No minimum frequency 1’b1: 50kHz
0	R/W	FCCM	1’b0	Sets forced continuous conduction mode (FCCM). 1’b0: Reserved 1’b1: FCCM

ILIM_SCALE (D2h)

Format: Unsigned binary

The ILIM_SCALE command on Page 0 sets the current limit (I_{LIMIT}) scale. For the MPQ2288 at a 16A I_{OUT}, the I_{LIMIT} scale should be set to 150%. Other options do not guarantee that the I_{LIMIT} parameters conform to the Electrical Characteristics section on page 6.

Bits	Access	Bit Name	Default	Description
7:2	R/W	RESERVED	-	Reserved.
1:0	R/W	ILIM_SCALE	2'b00	Sets the I_{LIMIT} scale. 2'b00: 50% 2'b01: 75% 2'b10: 100% 2'b11: 150%

ADDRESS (D3h)

Format: Unsigned binary

The ADDRESS command on Page 0 sets the address for digital interface communication.

Bits	Access	Bit Name	Default	Description
7	R/W	RESERVED	-	Reserved.
6:0	R/W	ADDRESS	7'b0000011	Sets the 7-bit digital interface address.

CONFIG_CODE (D4h)

Format: Unsigned binary

The CONFIG_CODE command on Page 0 returns the configuration code.

Bits	Access	Bit Name	Default	Description
7:0	R	CONFIG_CODE	8'b00000000	Returns the configuration code.

MEMORY_CRC (D5h)

Format: Unsigned binary

The MEMORY_CRC command on Page 0 returns the cyclic redundancy check (CRC) OTP data.

Bits	Access	Bit Name	Default	Description
15:0	R	MEMORY_CRC	16'b0000000000000000	Returns the CRC OTP data.

LATEST_PEC (D6h)

Format: Unsigned binary

The LATEST_PEC command on Page 0 returns the latest calculated packet error code from the previous write transition.

Bits	Access	Bit Name	Default	Description
7:0	R	LATEST_PEC	8'b00000000	Returns the latest calculated packet error code from the previous write transition.

MFR_OTP_MEM_STATUS (D8h)

Format: Unsigned binary

The MFR_OTP_MEM_STATUS command on Page 0 indicates whether certain OTP-related errors have occurred.

Bits	Access	Bit Name	Default	Description
7:3	R	RESERVED	-	Reserved.
2	R	STRUP_OTP_CRC_ERR	1'b0	0: No start-up load OTP CRC error has occurred 1: A start-up load OTP CRC error has occurred
1	R	STRUP_OTP_IND_ERR	1'b0	0: No start-up load OTP indicator error has occurred 1: A start-up load OTP indicator error has occurred
0	R	STORE_OTP_ERR	1'b0	0: No store OTP failure has occurred 1: A store OTP failure has occurred

ADVANCED_CONFIG (DBh)

Format: Unsigned binary

The ADVANCED_CONFIG command on Page 0 can enable advanced configuration read and write. The advanced configurations include the DCh and DDh registers.

Bits	Access	Bit Name	Default	Description
7:0	R/W	ADVANCED	-	8'b11100001: Enable advanced configuration read and write Others: Disable advanced configuration read and write

SUMMING_BLOCK_CONFIG (DCh)

Format: Unsigned binary

The SUMMING_BLOCK_CONFIG command on Page 0 sets loop performance parameters.

Bits	Access	Bit Name	Default	Description
7:6	R/W	RESERVED	-	Reserved.
5:3	R/W	CURRENT_SENSE_GAIN	3'b000	There are no units; this is a ratio compared to the nominal value of 1. 3'b000: 1 x ISENSE_GAIN_SCALE 3'b001: 0.75 x ISENSE_GAIN_SCALE 3'b010: 0.5 x ISENSE_GAIN_SCALE 3'b011: 0.25 x ISENSE_GAIN_SCALE 3'b100: 1.25 x ISENSE_GAIN_SCALE 3'b101: 1.5 x ISENSE_GAIN_SCALE 3'b110: 1.75 x ISENSE_GAIN_SCALE 3'b111: 2 x ISENSE_GAIN_SCALE
2:1	R/W	SLOPE_GM	2'b00	There are no units; this is a ratio compared to the nominal value of 1. 2'b00: 1 x SLOPE_GM_SCALE 2'b01: 0.5 x SLOPE_GM_SCALE 2'b10: 1.5 x SLOPE_GM_SCALE 2'b11: 2 x SLOPE_GM_SCALE
0	R/W	FB_GM	1'b0	Sets the FB_GM divider ratio. 1'b0: FB_GM divider = 1 1'b1: FB_GM divider = 2

MIN_ON_CONFIG (DDh)

Format: Unsigned binary

The MIN_ON_CONFIG command on Page 0 sets the minimum on time (t_{ON_MIN}) specifications and loop performance.

Bits	Access	Bit Name	Default	Description
7	R/W	ADAPTIVE_MIN_ON_FCCM	1’b0	Enables the adaptive t_{ON_MIN} during FCCM. 1’b0: Enabled 1’b1: Disabled
6	R/W	ADAPTIVE_MIN_ON_SS	1’b0	Enables the adaptive t_{ON_MIN} during soft start (SS). 1’b0: Enabled 1’b1: Disabled
5	R/W	ISENSE_GAIN_SCALE	1’b0	Sets the CURRENT_SENSE_GAIN scale. 1’b0: 1 1’b1: 2
4	R/W	SLOPE_GM_SCALE	1’b0	Set the SLOPE_GM scale. 1’b0: 1 1’b1: 2
3	R/W	RESERVED	-	Reserved.
2:0	R/W	ADAPTIVE_MIN_ON	3’b000	Sets the t_{ON_MIN} parameter. There are no units; this is a ratio compared to the nominal value of 1. The smaller the ratio, the greater t_{ON_MIN}. 3’b000: 1 3’b001: 0.8 3’b010: 0.6 3’b011: 0.4 3’b100: 1 3’b101: 1.2 3’b110: 1.4 3’b111: 1.6

APPLICATION INFORMATION

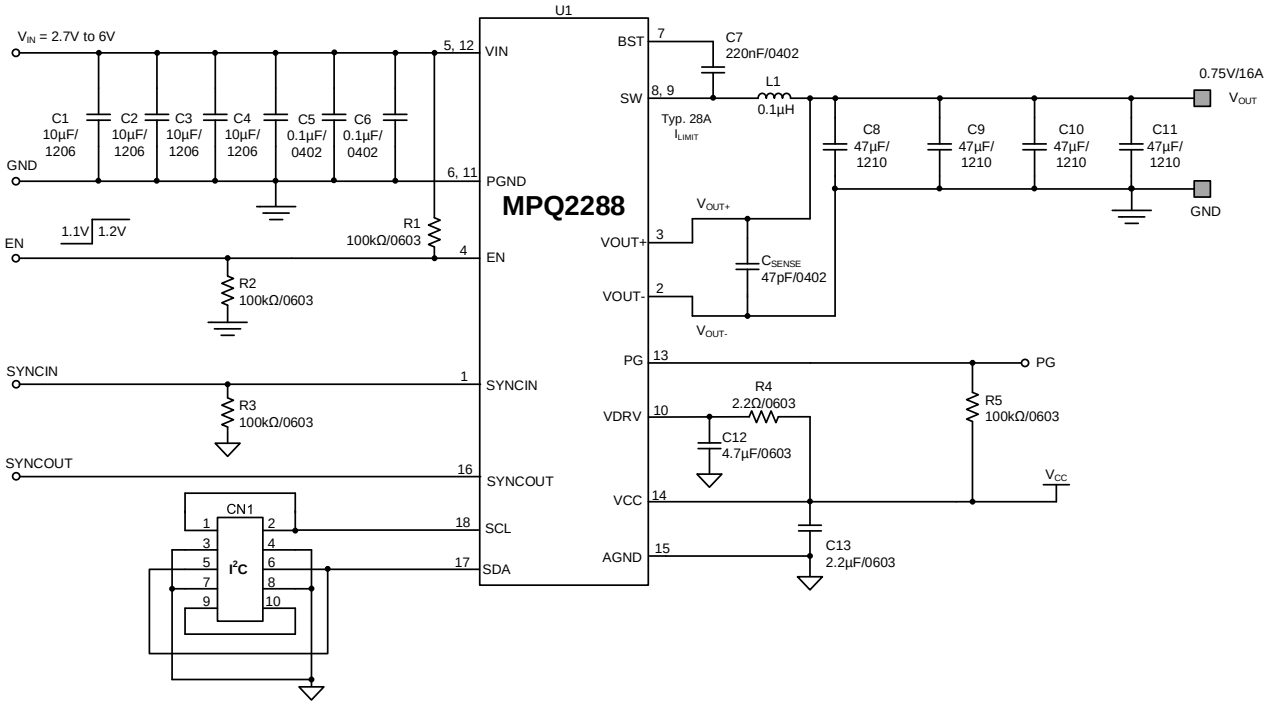


Figure 11: Typical Application Circuit (V_{OUT} = 0.75V, f_{SW} = 3MHz)

Table 2: Design Guide Index

Pin #	Pin Name	Component	Design Guide Index
1	SYNCIN	R3	External Synchronous Input (SYNCIN, Pin 1)
2	VOUT-	C_{SENSE}	Setting the Output Voltage (VOUT-, Pin 2; VOUT+, Pin 3)
3	VOUT+	C_{SENSE}	Setting the Output Voltage (VOUT-, Pin 2; VOUT+, Pin 3)
4	EN	R1, R2	Enable (EN, Pin 4)
5, 12	VIN	C1, C2, C3, C4, C5, C6	Selecting the Input Capacitor (VIN, Pins 5 and 12)
6, 11	PGND	-	GND Connection (PGND, Pin 6 and 11; AGND, Pin 15)
15	AGND	-	GND Connection (PGND, Pin 6 and 11; AGND, Pin 15)
7	BST	C7	Floating Driver and Bootstrap Charging (BST, Pin 7)
8, 9	SW	L1, C8, C9, C10, C11	Selecting the Inductor and Output Capacitor (SW, Pins 8 and 9)
10	VDRV	C12	Internal LDO Output (VDRV, Pin 10)
13	PG	R5	Power Good indicator (PG, Pin 13)
14	VCC	R4, C13	Supply Input for the Internal Analog and Digital Circuits (VCC, Pin 14)
16	SYNCOUT	-	SYNC Output (SYNCOUT, Pin 16)
17	SDA	-	Digital Interface (SDA, Pin 17; SCL, Pin 18)
18	SCL	-	Digital Interface (SDA, Pin 17; SCL, Pin 18)

External Synchronous Input (SYNCIN, Pin 1)

When the external clock signal is connected to the SYNCIN pin, the switching frequency (f_{SW}) can be synchronized to the rising edge. The SYNC clock's high amplitude should exceed 1.8V, and its low amplitude should be below 0.4V to drive the internal logic. The recommended external SYNC frequency is ±15% the set f_{SW} (between 2MHz and 4MHz.

Setting the Output Voltage (VOUT-, Pin 2; VOUT+, Pin 3)

The one-time programmable (OTP) memory registers VOUT_COMMAND and VOUT_SCALE_LOOP set V_{OUT}.

Write to VOUT_COMMAND (21h), bits[7:0] (VOUT_CMD), and VOUT_SCALE_LOOP (29h), bit[0] (VOUT_SC_L) to set V_{OUT}. V_{OUT} can be calculated with Equation (1):

$$V_{OUT}\ (mV) = (VOUT\_CMD \times 6.25 + 206.25) \times VOUT\_SL \quad (1)$$

Set VOUT_SC_L to 0 when V_{OUT} is between 0.5V and 1.8V. If V_{OUT} is between 1.8V and 3.6V, set VOUT_SC_L to 1. V_{OUT} must be disabled via the digital interface when writing to VOUT_SC_L in register VOUT_SCALE_LOOP.

It is recommended to use another, lower-value capacitor (e.g. 47pF) with a small package size (0402) to absorb high-frequency switching noise. Place the smaller capacitor as close to the VOUT+ and VOUT- pins as possible.

For V_{OUT} configuration, avoid V_{OUT} being below 0.5V.

Enable (EN, Pin 4)

EN is a digital control pin that turns the converter on and off. When the EN voltage (V_{EN}) exceeds 0.65V, the VDRV supply turns on. In this scenario, digital interface communication operates normally, and the host can read/write to the MPQ2288's registers normally. When V_{EN} exceeds 1.2V, the MPQ2288 turns on.

Selecting the Input Capacitor (VIN, Pin 5 and 12)

The step-down converter has a discontinuous input current (I_{IN}), and requires a capacitor to supply AC current to the converter while maintaining the DC V_{IN}. For the best performance, use low-ESR capacitors. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients.

It is recommended to use another, lower-value capacitor (e.g. 0.1µF) with a small package size (0603) to absorb high-frequency switching noise. Place the smaller capacitor as close to the VIN and GND pins as possible.

Since the input capacitor (C_{IN}) absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in C_{IN} (I_{CIN}) can be estimated with Equation (2):

$$I_{CIN} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}})} \quad (2)$$

The worst-case condition occurs at V_{IN} = 2 x V_{OUT}, calculated with Equation (3):

$$I_{CIN} = \frac{I_{LOAD}}{2} \quad (3)$$

For simplification, choose C_{IN} to have an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using electrolytic or tantalum capacitors, add a small, high-quality ceramic capacitor (e.g. 0.1µF) as close to the IC as possible. When using ceramic capacitors, ensure that they have enough capacitance to provide a sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple (ΔV_{IN}) caused by the capacitance can be estimated with Equation (4):

$$\Delta V_{IN} = \frac{I_{LOAD}}{f_{SW} \times C_{IN}} \times \frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (4)$$

GND Connection (PGND, Pin 6 and 11; AGND Pin 15)

See the PCB Layout Guidelines section on page 57 for more details.

Floating Driver and Bootstrap Charging (BST, Pin 7)

The BST capacitor (C7, also referred to as C_{BST}) is recommended to be 0.22µF.

C_{BST} is charged and regulated to about 3.3V by the dedicated internal BST regulator. When the voltage between the BST and SW nodes is below its regulated value (2.75V), a transistor

connected from the VDRV to BST pins turns on to charge C_{BST}.

When the HS-FET is on, the BST voltage (V_{BST}) exceeds the VDRV voltage (V_{DRV}), so C_{BST} cannot be charged. At higher duty cycles, the time available to charge C_{BST} is shorter, so it may not be charged sufficiently. In this scenario, the bootstrap refresh circuit turns the HS-FET off and turns the LS-FET on to ensure that C_{BST} is properly charged.

Selecting the Inductor and Output Capacitor (SW, Pin 8 and 9)

Selecting the Output Capacitor

The output voltage ripple (ΔV_{OUT}) can be calculated with Equation (5):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \times (R_{ESR} + \frac{1}{8 \times f_{SW} \times C_{OUT}}) \quad (5)$$

Where L is the inductance, and R_{ESR} is the equivalent series resistance (ESR) of the output capacitor (C_{OUT}).

For ceramic capacitors, the capacitance dominates the impedance at f_{SW} and causes the majority of ΔV_{OUT}. For simplification, ΔV_{OUT} can be estimated with Equation (6):

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_{SW}^{2} \times L \times C_{OUT}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (6)$$

For tantalum or electrolytic capacitors, the ESR dominates the impedance at f_{SW}. For simplification, ΔV_{OUT} can be calculated with Equation (7):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \times R_{ESR} \quad (7)$$

The characteristics of C_{OUT} also affect the stability of the regulation system. The MPQ2288 can be optimized for a wide range of capacitances and ESR values.

Selecting the Inductor

An inductor with a DC current rating at least 25% greater than the maximum load current is recommended for most applications. For higher efficiency, choose an inductor with a lower DC resistance. A larger-value inductor results in less ripple current and a lower ΔV_{OUT}, but also has a larger physical size, higher series resistance, and lower saturation current. A good rule to determine the inductance is to allow the inductor ripple current to be approximately 30% of the maximum load current. The inductance (L) can be estimated with Equation (8):

$$L = \frac{V_{OUT}}{f_{SW} \times \Delta I_{L}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (8)$$

Where ΔI_L is the peak-to-peak inductor ripple current.

Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum peak inductor current (I_{L_PEAK}) can be calculated with Equation (9):

$$I_{LP} = I_{LOAD} + \frac{V_{OUT}}{2 \times f_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (9)$$

Internal LDO Output (VDRV, Pin 10)

The VDRV capacitor (C12) is recommended to be about 4.7µF.

The high-side (HS) and low-side (LS) drive circuits are powered by the internal VDRV regulator. This regulator uses the VIN pin as its input and operates across the entire V_{IN} range. When V_{IN} exceeds 3.3V, VDRV is in full regulation. When V_{IN} is below 3.3V, the VDRV output degrades.

Power Good (PG) Indicator (PG, Pin 13)

The PG pin is an open-drain output. If using the PG pin, connect PG to VCC via a pull-up resistor (R5, which is recommend to be about 100kΩ).

PG asserts (pulls low) if the output power (POUT) is outside of the PG thresholds. The PG threshold can be configured by writing to PG_CONFIG (D0h), bit[0] (PG_THRESHOLD). The PG threshold is ±4% when PG_THRESHOLD is set to 0. The PG threshold is ±6% when PG_THRESHOLD is set to 1. See the Power Good (PG) Indicator section on page 32 for more information on the PG pin's state.

Supply Input for the Internal Analog and Digital Circuits (VCC, Pin 14)

Connect the VDRV supply to the VCC pin using a 2.2Ω resistor. Decouple the VCC pin using a 2.2µF capacitor connected to AGND. The internal analog and digital circuits are powered by VCC, except for the HS and LS drive circuits.

SYNC Output (SYNCOUT, Pin 16)

The SYNCOUT pin can output the internal clock with 0° or 180° phase shift. This phase shift can be configured via FREQUENCY_SET (CBh), bit[2] (SYNCO_PHASE).

Digital Interface (SDA, Pin 17; SCL, Pin 18)

The MPQ2288 works as a slave-only device which supports fast-mode plus (1Mbps) bidirectional data transfer, adding flexibility to the power supply solution. See the Digital Interface section on page 35 for details.

The SCL and SDA lines are externally pulled to a bus voltage using a resistor (e.g. 1.5kΩ).

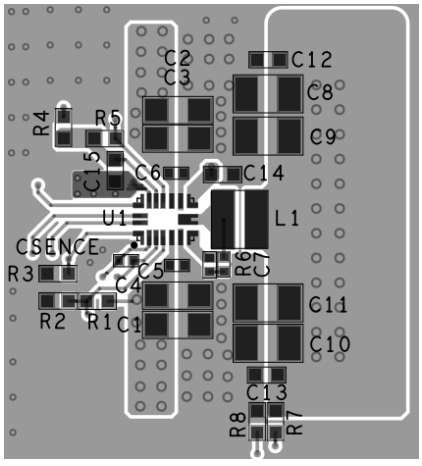
PCB Layout Guidelines (14)

Efficient PCB layout, especially input capacitor placement, is critical for stable operation. A 4-layer layout is strongly recommended to improve thermal performance. For the best results, refer to Figure 12 and follow the guidelines below:

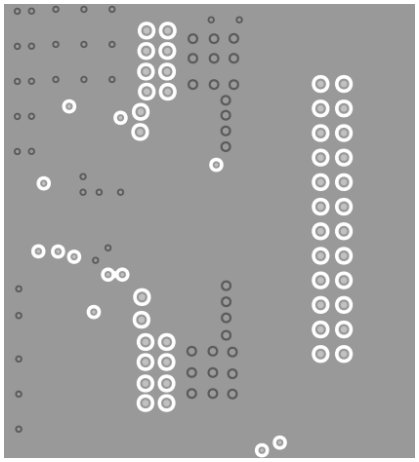
1. Place the symmetric input capacitors as close to the VIN and GND pins as possible.
2. Connect a large ground plane directly to PGND.
3. Ensure that the high-current paths at GND and VIN have short, direct, and wide traces.
4. Place the ceramic input capacitor (C_{IN}), especially the small package size (0603) input bypass capacitor, as close to the VIN and PGND pins as possible to minimize high-frequency noise.
5. Keep the connection between C_{IN} and VIN as short and wide as possible.
6. Place the VCC capacitor (C_{VCC}) as close to the VCC and GND pins as possible.
7. Route SW away from sensitive analog areas, such as FB.
8. Ensure that the trace between FB and the output is as short as possible.
9. Use multiple vias to connect the power planes to the internal layers.

Notes:

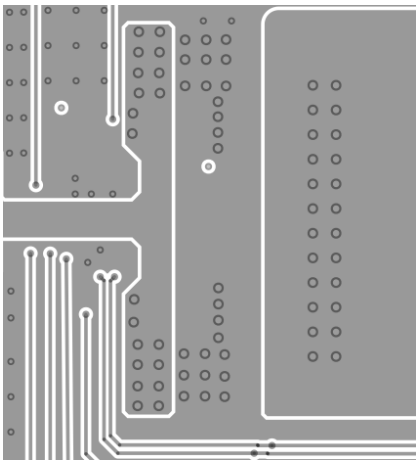
14) The recommended PCB layout is based on Figure 14 on page 58.



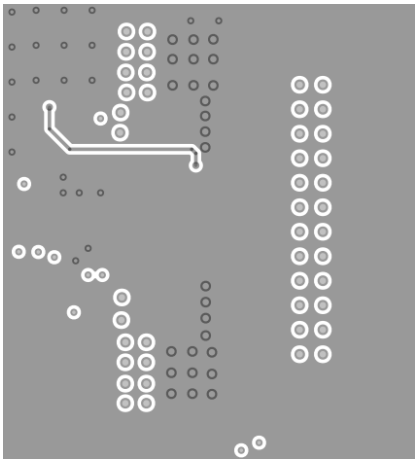
Top Layer



Mid-Layer 1



Mid-Layer 2



Bottom Layer

Figure 12: Recommended PCB Layout

TYPICAL APPLICATION CIRCUITS

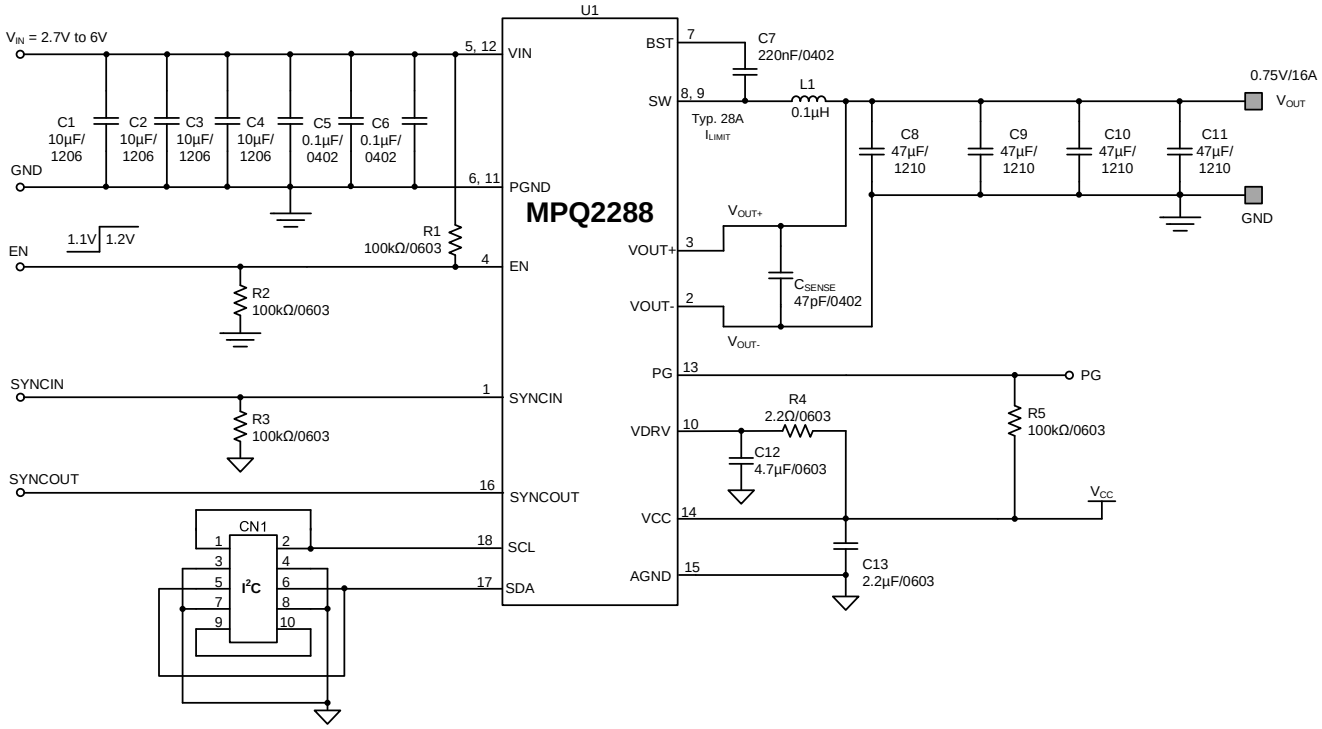


Figure 13: Typical Application Circuit (V_{OUT} = 0.75V, I_{OUT} = 16A, f_{SW} = 3MHz)

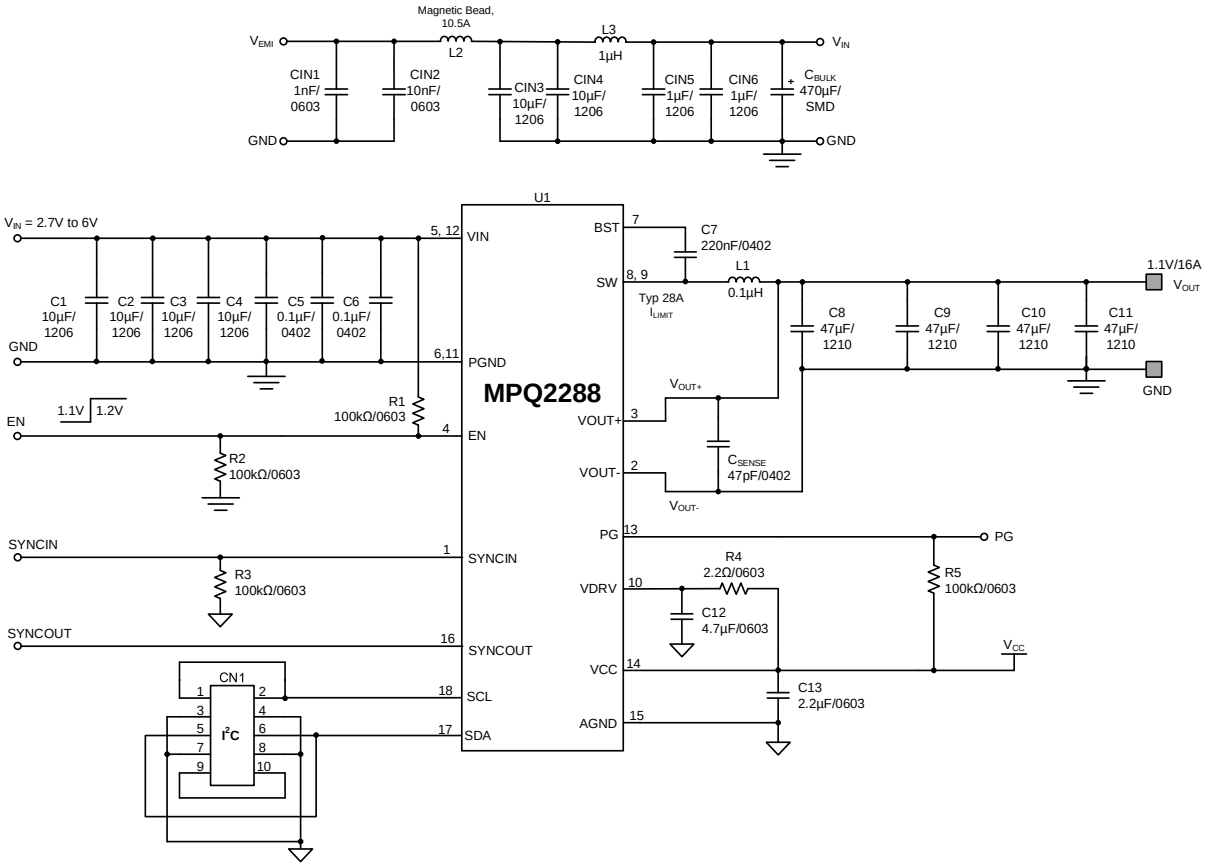
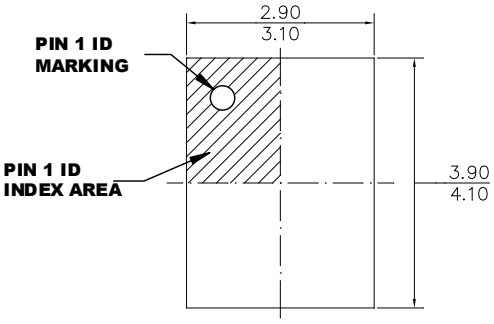


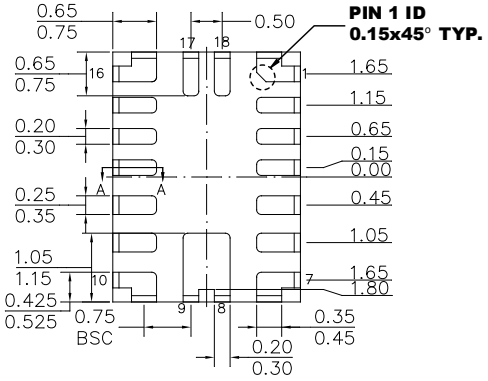
Figure 14: Typical Application Circuit (V_{OUT} = 1.1V, I_{OUT} = 16A, f_{SW} = 4MHz with EMI Filter)

PACKAGE INFORMATION

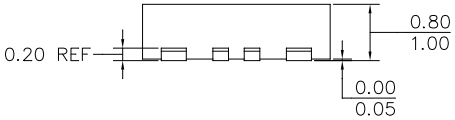
QFN-18 (3mmx4mm)
Wettable Flank



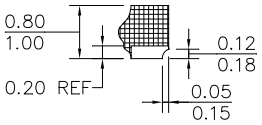
TOP VIEW



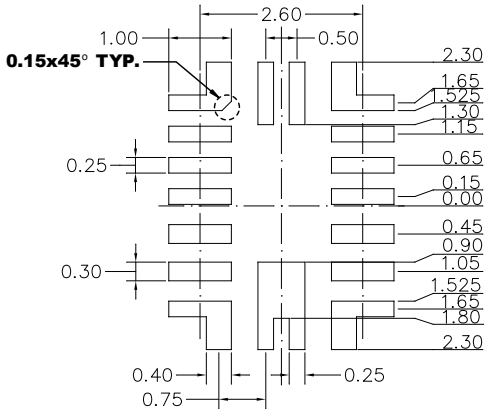
BOTTOM VIEW



SIDE VIEW



SECTION A-A

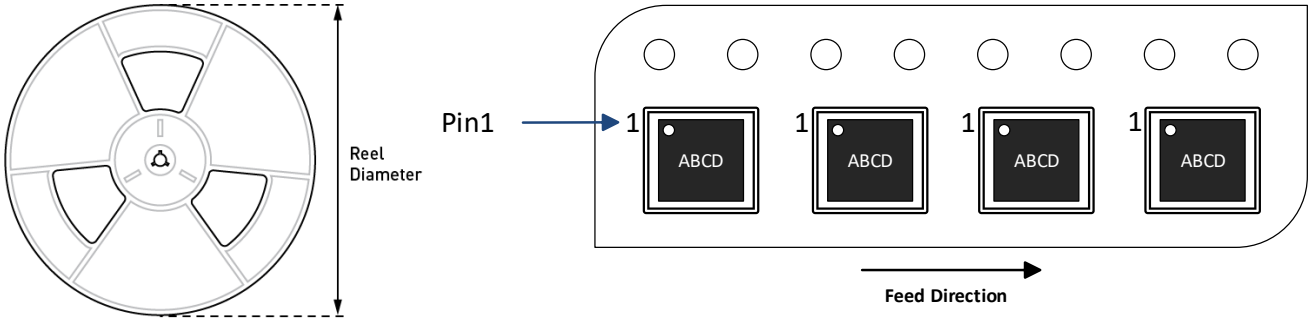


RECOMMENDED LAND PATTERN

NOTE:

1)THE LEAD SIDE IS WETTABLE.
2) ALL DIMENSIONS ARE IN MILLIMETERS.
3) LEAD COPLANARITY SHALL BE 0.08 MILLIMETERS MAX.
4) JEDEC REFERENCE IS MO-220.
5) DRAWING IS NOT TO SCALE.

CARRIER INFORMATION



Part Number	Package Description	Quantity/ Reel	Quantity/ Tube	Quantity/ Tray	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch
MPQ2288GLE-xxxx-AEC1-Z	QFN-18 (3mmx4mm)	5000	N/A	N/A	13in	12mm	8mm

REVISION HISTORY

Revision #	Revision Date	Description	Pages Updated
1.0	2/7/2025	Initial Release	-